Networking Fire Protection Flash MCU

BA45FH0082

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Features

CPU Features

- Operating Voltage
  - f_{SYS} = 2MHz: 2.2V~5.5V
  - f_{SYS} = 4MHz: 2.2V~5.5V
- Up to 1μs instruction cycle with 4MHz system clock at V_{DD}=5V
- Power down and wake-up functions to reduce power consumption
- Oscillators:
  - Internal High Speed 2/4MHz RC Oscillator – HIRC
  - Internal Low Speed 32kHz RC Oscillator – LIRC
- Fully integrated internal oscillators require no external components
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- All instructions executed in 1~2 instruction cycles
- Table read instructions
- 63 powerful instructions
- 6-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 2K×15
- RAM Data Memory: 128×8
- True EEPROM Memory: 64×8
- Watchdog Timer function
- Up to 13 bidirectional I/O lines
- Single external interrupt line shared with I/O pin
- Two Timer Modules for time measurement, input capture, compare match output, PWM output function or single pulse output function
- 8 external channels 12-bit resolution A/D converter
- Dual Time-Base functions for generation of fixed time interrupt signals
- Low voltage reset function – LVR
- Low voltage detect function – LVD
- Package types: 16-pin NSOP, 20-pin SSOP

Two Line Power Line Data Transceiver Features

- Complete Data Transmission on Power Line functions
- High Maximum Input Voltage: 42V
- Integrated Low Dropout Voltage Regulator
- Integrated Low Voltage Detector for Power Supply Monitoring
- Integrated Comparator
- Open drain NMOS driver for flexible interfacing
- Power and Reset Protection Features
- Minimal external component requirements

General Description

The BA45FH0082 is a Flash Memory 8-bit high performance RISC architecture microcontrollers, designed for networking type fire protection peripheral products. Offering users the convenience of Flash Memory multi-programming features, the device also includes a wide range of functions and features. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

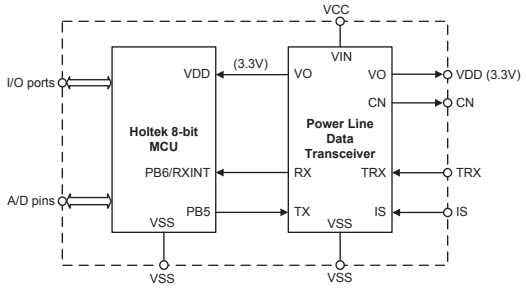
Analog feature includes a multi-channel 12-bit A/D converter. Multiple and extremely flexible Timer Modules provide timing, pulse generation and PWM generation functions. Protective features such as an internal Watchdog Timer, Low Voltage Reset and Low Voltage Detector coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

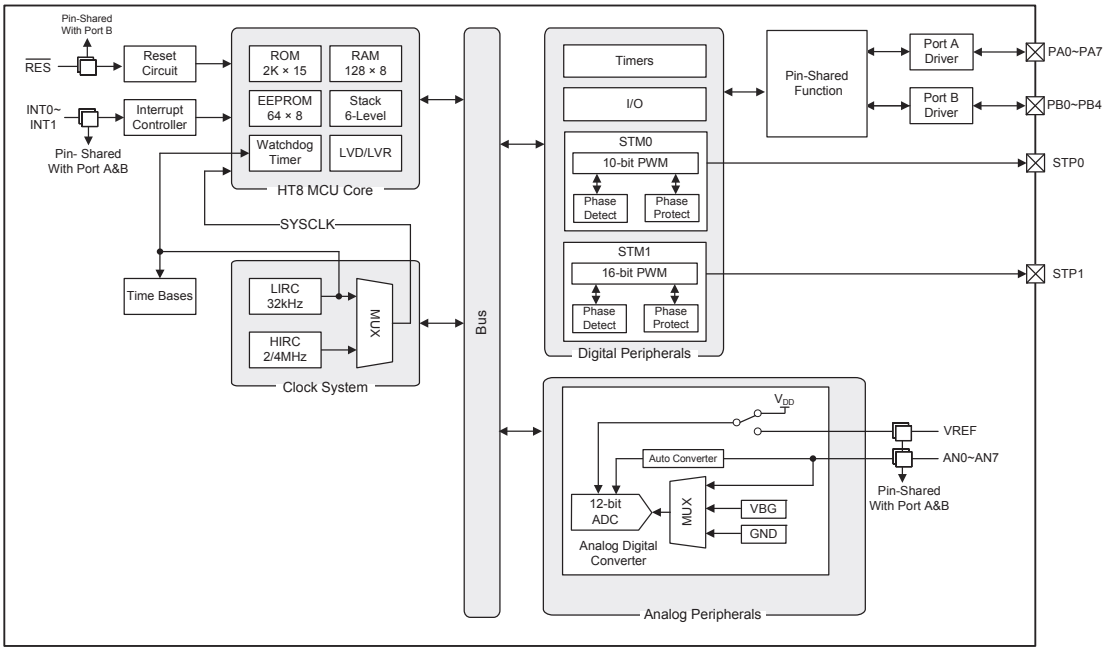
The device also contain a two line type power line data transceiver. In systems where a master controller controls a number of individual interconnected subsystems such as found in smoke detector systems, water metering systems, solar energy system, etc., the cost of the lengthy interconnecting cabling can be a major factor. By sending data along the power supply lines, the interconnecting cables can be reduced to a simple two line type, thus greatly reducing both cable and installation costs. With the addition of a few external components, this power line data transceiver device contains all the internal components required to provide users with a system for power line data transmission and reception. Data is modulated onto the power line by the simple reduction of the power line voltage for a specific period of time. Power supply voltage changes can be initiated by the master controller for data reception or initiated by the power line data transceiver for data transmission. An internal voltage regulator with a Soft-start and short circuit protection functions ensures that a constant voltage power supply is provided to the interconnected subsystem units while an internal voltage detector monitors the power line voltage level. An internal comparator is used to translate the differential signal into a logic signal for the MCU.

A full choice of internal low and high oscillator functions are provided, the fully integrated system oscillators require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise microcontroller operation and minimise power consumption.

The inclusion of flexible I/O programming features, Time-Base functions along with many other features ensure that the device will find excellent use in fire protection peripheral applications such as Temperature alarms, Output/Input modules, Acousto-optic alarms, Fire door monitors in addition to many others.

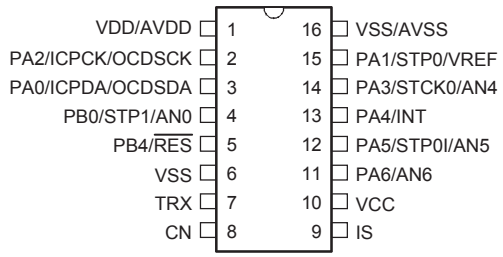
Block Diagram



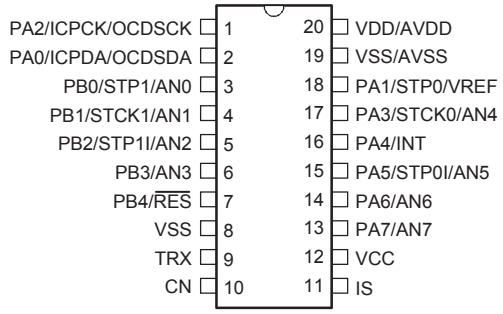


: Pin-Shared Node

Pin Assignment



BA45FH0082/BA45VH0082
16 NSOP-A



BA45FH0082/BA45VH0082
20 SSOP-A

Note: 1. If the pin-shared pin functions have multiple outputs, the desired pin-shared function is determined by the corresponding software control bits.
2. The OCDSDA and OCDSCK pins are supplied as OCDS dedicated pins and as such only available for the BA45VH0082 device which is the OCDS EV chip for the BA45FH0082 device.
3. For less pin-count package types there will be unbonded pins of which status should be properly configured to avoid the current consumption resulting from an input floating condition. Refer to the “Standby Current Considerations” and “Input/Output Ports” sections.

Pin Description

With the exception of the power pins and some relavant transformer control pins, all pins on the device can be referenced by their Port names, e.g. PA0, PA1 etc, which refer to the digital I/O function of the pins. However these Port pins are also shared with other function such as the Timer Module pins etc. The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet. Note that where more than one package type exists the table will reflect the situation for the larger package type.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/ICPDA/ OCDSDA	PA0	PAWU PAPU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	ICPDA	—	ST	CMOS	ICP data/address
	OCDSDA	—	ST	CMOS	OCDS data/address, for EV chip only.
PA1/STP0/VREF	PA1	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	STP0	PAS0	—	CMOS	STM0 non-inverting output
	VREF	PAS0	AN	—	A/D converter extemal reference input
PA2/ICPCK/ OCDSCK	PA2	PAWU PAPU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	ICPCK	—	ST	—	ICP clock input
	OCDSCK	—	ST	—	OCDS clock input, for EV chip only
PA3/STCK0/AN4	PA3	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	STCK0	PAS0	ST	—	STM0 clock input
	AN4	PAS0	AN	—	A/D converter analog input
PA4/INT	PA4	PAWU PAPU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	INT	INTEG INTC0	ST	—	External interrupt input
PA5/STP0I/AN5	PA5	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	STP0I	PAS1	ST	—	STM0 capture input
	AN5	PAS1	AN	—	A/D converter analog input
PA6/AN6	PA6	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	AN6	PAS1	AN	—	A/D converter analog input
PA7/AN7	PA7	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	AN7	PAS1	AN	—	A/D converter analog input
PB0/STP1/AN0	PB0	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up.
	STP1	PBS0	ST	—	STM1 non-inverting output
	AN0	PBS0	AN	—	A/D converter analog input
PB1/STCK1/AN1	PB1	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up.
	STCK1	PBS0	ST	—	STM1 clock input
	AN1	PBS0	AN	—	A/D converter analog input

Pin Name	Function	OPT	I/T	O/T	Description
PB2/STP1I/AN2	PB2	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up.
	STP1I	PBS0	ST	—	STM1 capture input
	AN2	PBS0	AN	—	A/D converter analog input
PB3/AN3	PB3	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up.
	AN3	PBS0	AN	—	A/D converter analog input
PB4/$\overline{\text{RES}}$	PB4	PBPU	ST	CMOS	General purpose I/O. Register enabled pull-up.
	$\overline{\text{RES}}$	RSTC	ST	—	External reset input
CN	CN	—	AN	—	Comparator negative input
IS	IS	—	—	NMOS	Source terminal of constant current NMOS driver
TRX	TRX	—	DI	DO	Transceiver signal detect/modulate
VCC	VCC	—	PWR	—	Power line data transceiver LDO input
VSS	VSS	—	PWR	—	Power line data transceiver negative power supply, ground.
VDD/AVDD	VDD	—	PWR	—	Power line data transceiver LDO output, MCU digital positive power supply.
	AVDD	—	PWR	—	Analog positive power supply.
VSS/AVSS	VSS	—	PWR	—	MCU digital negative power supply.
	AVSS	—	PWR	—	Analog negative power supply, ground.

Legend: I/T: Input type
O/T: Output type
OPT: Optional by register option
ST: Schmitt Trigger input
CMOS: CMOS output
NMOS: NMOS output
AN: Analog signal
PWR: Power
DI: Digital input
DO: Digital output

Internally Connected Pins

Among the pins mentioned in the tables above several pins are not connected to external package pins. These pins are interconnection pins between the MCU and the power line data transceiver chip and are listed in the following table. The description is provided from the power line data transceiver chip standpoint.

Power Line Data Transceiver Pin Name	Type	Description
RX	O	Comparator output, transmitter signal detect output Internally connected to the MCU I/O line, PB6/RXINT
TX	I	Input pin for constant current modulate Internally connected to the MCU I/O line, PB5
VO	PWR	LDO output Connected to MCU positive power supply, VDD

Absolute Maximum Ratings

Supply Voltage ..... V_{SS}-0.3V to V_{SS}+6.0V
Input Voltage ..... V_{SS}-0.3V to V_{DD}+0.3V
Storage Temperature..... -50°C to 125°C
Operating Temperature..... -40°C to 85°C
I_{OL} Total 80mA
I_{OH} Total ..... -80mA
Total Power Dissipation 500mW

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, etc., can all exert an influence on the measured values.

Operating Voltage Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	f_{SYS} = 2MHz	2.2	—	5.5	V
		f_{SYS} = 4MHz	2.2	—	5.5	
	Operating Voltage – LIRC	f_{SYS} = 32kHz	2.2	—	5.5	V

Standby Current Characteristics

Ta=25°C

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V_{DD}	Conditions					
I_{STB}	SLEEP Mode	2.2V	WDT off	—	0.2	0.6	0.7	μA
		3V		—	0.2	0.8	1	
		5V		—	0.5	1	1.2	
		2.2V	WDT on	—	1.2	2.4	2.9	
		3V		—	1.5	3	3.6	
		5V		—	3	5	6	
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	2.4	4	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	2.2V	f_{SUB} on, f_{SYS} = 2MHz	—	0.06	0.12	0.14	mA
		3V		—	0.07	0.14	0.16	
		5V		—	0.13	0.26	0.28	
		2.2V	f_{SUB} on, f_{SYS} = 4MHz	—	0.09	0.20	0.22	
		3V		—	0.11	0.22	0.24	
		5V		—	0.21	0.42	0.46	

Notes: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Standby Current values are taken after a HALT instruction execution thus stopping all instruction execution.

Operating Current Characteristics

Ta=25°C

Symbol	Operating Mode	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{DD}	SLOW Mode – LIRC	2.2V	f_{SYS} = 32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	2.2V	f_{SYS} = 2MHz	—	0.15	0.2	mA
		3V		—	0.2	0.3	
		5V		—	0.4	0.6	
		2.2V	f_{SYS} = 4MHz	—	0.3	0.5	
		3V		—	0.4	0.6	
		5V		—	0.8	1.2	

Notes: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of either 3V or 5V.

2/4MHz

Symbol	Parameter	Test Conditions		Min	Typ	Max	Unit
		V_{DD}	Temp.				
f_{HIRC}	2MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	2	+1%	MHz
			-20°C~60°C	-2%	2	+2%	
			-40°C~85°C	-3%	2	+3%	
		2.2V~5.5V	25°C	-9%	2	+9%	
			-40°C~85°C	-10%	2	+10%	
	4MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	4	+1%	MHz
			-40°C~85°C	-2%	4	+2%	
		2.2V~5.5V	25°C	-2.5%	4	+2.5%	
			-40°C~85°C	-3%	4	+3%	

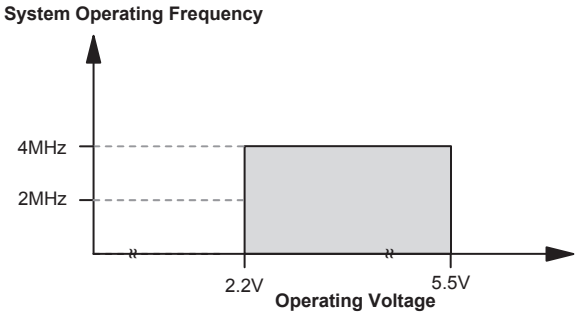
Notes: 1. The 3V/5V values for V_{DD} are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.
2. The row below the 3V/5V trim voltage row is provided to show the values for the full V_{DD} range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 2.2V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.
3. The minimum and maximum tolerance values provided in the table are only for the frequency at which the writer trims the HIRC oscillator. After trimming at this chosen specific frequency any change in HIRC oscillator frequency using the oscillator register control bits by the application program will give a frequency tolerance to within ±20%.

Low Speed Internal Oscillator Characteristics – LIRC

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
f_{LIRC}	LIRC Frequency	2.2V~5.5V	25°C	-10%	32	+10%	kHz
			-40°C~85°C	-50%	32	+60%	
t_{START}	LIRC Start Up Time	—	—	—	—	500	μs

Operating Frequency Characteristic Curves



System Start Up Time Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{SST}	System Start-up Time Wake-up from Condition where f_{SYS} is Off	—	$f_{SYS} = f_H \sim f_H/64$, $f_H = f_{HIRC}$	—	16	—	t_{HIRC}
		—	$f_{SYS} = f_{SUB} = f_{LIRC}$	—	2	—	t_{LIRC}
	System Start-up Time Wake-up from Condition where f_{SYS} is On	—	$f_{SYS} = f_H \sim f_H/64$, $f_H = f_{HIRC}$	—	2	—	t_H
		—	$f_{SYS} = f_{SUB} = f_{LIRC}$	—	2	—	t_{SUB}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f_{HIRC} switches from off → on	—	16	—	t_{HIRC}
t_{RSTD}	System Reset Delay Time Reset Source from Power-on Reset or LVR Hardware Reset	—	RR_{POR} = 5V/ms	42	48	54	ms
	System Reset Delay Time WDTC/RSTC Software Reset	—	—				
	System Reset Delay Time Reset Source from WDT Overflow or Reset Pin Reset	—	—	8	16	24	ms

Notes: 1. For the System Start-up time values, whether f_{SYS} is on or off depends upon the mode type and the chosen f_{SYS} system oscillator. Details are provided in the System Operating Modes section.

2. The time units, shown by the symbols t_{HIRC}. are the inverse of the corresponding frequency values as provided in the frequency tables. For example $t_{HIRC} = 1/f_{HIRC}$, $t_{SYS} = 1/f_{SYS}$ etc.

3. If the LIRC is used as the system clock and if it is off when in the SLEEP Mode, then an additional LIRC start up time, t_{START}, as provided in the LIRC frequency table, must be added to the t_{SST} time in the table above.

4. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IL}	Input Low Voltage for I/O Ports or Input Pins	5V	—	0	—	1.5	V
		—	—	0	—	$0.2V_{DD}$	
	Input Low Voltage for External Reset Pin	—	—	0	—	$0.4V_{DD}$	
V_{IH}	Input High Voltage for I/O Ports or Input Pins	5V	—	3.5	—	5.0	V
		—	—	$0.8V_{DD}$	—	V_{DD}	
	Input High Voltage for External Reset Pin	—	—	$0.9V_{DD}$	—	V_{DD}	
I_{OL}	Sink Current for I/O Pins	3V	V_{OL} = $0.1V_{DD}$	15.5	31	—	mA
		5V		31	62	—	
I_{OH}	Source Current for I/O Pins	3V	V_{OH} = $0.9V_{DD}$	-3.5	-7.0	—	mA
		5V		-7.2	-14.5	—	
R_{PH}	Pull-high Resistance for I/O Ports(Note)	3V	—	20	60	100	kΩ
		5V		10	30	50	
I_{LEAK}	Input Leakage Current	5V	V_{IN} = V_{DD} or V_{IN} = V_{SS}	—	—	±1	μA
t_{TPI}	TM Capture Input Minimum Pulse Width	—	—	0.3	—	—	μs
t_{TCK}	TM Clock Input Minimum Pulse Width	—	—	0.3	—	—	μs
t_{INT}	Interrupt Input Pin Minimum Pulse Width	—	—	10	—	—	μs
t_{RES}	External Reset Pin Minimum Pulse Width	—	—	10	—	—	μs
t_{SRESET}	Minimum Software Reset Pulse Width to Reset	—	—	45	90	120	μs

Note: The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-high resistor and then measuring the input sink current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.

Memory Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{RW}	V_{DD} for Read / Write	—	—	V_{DDmin}	—	V_{DDmax}	V
Flash Program Memory / Data EEPROM Memory							
t_{DEW}	Data EEPROM Write Cycle Time	—	—	—	4	6	ms
I_{DDPGM}	Programming / Erase Current on V_{DD}	—	—	—	—	5.0	mA
E_P	Cell Endurance – Flash Program Memory	—	—	10K	—	—	E/W
	Cell Endurance – Data EEPROM Memory	—	—	100K	—	—	E/W
t_{RETD}	ROM Data Retention Time	—	Ta = 25°C	—	40	—	Year
RAM Data Memory							
V_{DR}	RAM Data Retention Voltage	—	Device in SLEEP Mode	1.0	—	—	V

LVD/LVR Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{LVR}	Low Voltage Reset Voltage	—	LVR enable	-5%	2.1	+5%	V
V_{LVD}	Low Voltage Detection Voltage	—	LVD enable, voltage select 2.0V	-5%	2.0	+5%	V
			LVD enable, voltage select 2.2V		2.2		
			LVD enable, voltage select 2.4V		2.4		
			LVD enable, voltage select 2.7V		2.7		
			LVD enable, voltage select 3.0V		3.0		
			LVD enable, voltage select 3.3V		3.3		
			LVD enable, voltage select 3.6V		3.6		
			LVD enable, voltage select 4.0V		4.0		
$I_{LVRLVDBG}$	Operating Current	3V	LVD enable, LVR enable, VBGEN=0	—	—	18	μA
		5V		—	20	25	
		3V	LVD enable, LVR enable, VBGEN=1	—	—	150	
		5V		—	180	200	
t_{LVDS}	LVDO Stable Time	—	For LVR enable, VBGEN=0, LVD off → on	—	—	15	μs
		—	For LVR disable, VBGEN=0, LVD off → on	—	—	150	
t_{LVR}	Minimum Low Voltage Width to Reset	—	—	120	240	480	μs
t_{LVD}	Minimum Low Voltage Width to Interrupt	—	—	60	120	240	μs
I_{LVR}	Additional Current for LVR Enable	—	LVD disable, VBGEN=0	—	—	24	μA
I_{LVD}	Additional Current for LVD Enable	—	LVR disable, VBGEN=0	—	—	24	μA

Reference Voltage Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{BG}	Bandgap Reference Voltage	—	—	-5%	1.04	+5%	V
t_{BGS}	V_{BG} Turn On Stable Time	—	No load	—	—	150	μs
I_{BG}	Additional Current for V_{BG} Enable	—	LVR disable, LVD disable	—	—	180	μA

Note: The V_{BG} voltage can be used as the A/D converter internal signal input.

A/D Converter Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.2	—	5.5	V
V_{ADI}	Input Voltage	—	—	0	—	V_{REF}	V
V_{REF}	Reference Voltage	—	—	2	—	V_{DD}	V
DNL	Differential Non-linearity	3V	V_{REF} = V_{DD}, t_{ADCK} = 0.5μs	—	—	±3	LSB
		5V					
		3V	V_{REF} = V_{DD}, t_{ADCK} = 8μs				
		5V					
INL	Integral Non-linearity	3V	V_{REF} = V_{DD}, t_{ADCK} = 0.5μs	—	—	±4	LSB
		5V					
		3V	V_{REF} = V_{DD}, t_{ADCK} = 8μs				
		5V					
I_{ADC}	Additional Current for ADC Enable	3V	No load (t_{ADCK} = 0.5μs)	—	1	2	mA
		5V		—	1.5	3	mA
t_{ADCK}	Clock Period	—	—	0.5	—	10	μs
t_{ON2ST}	ADC On-to-Start Time	—	—	4	—	—	μs
t_{ADS}	Sampling Time	—	—	—	4	—	t_{ADCK}
t_{ADC}	Conversion Time (Include ADC Sample and Hold Time)	—	—	—	16	—	t_{ADCK}

Power Line Data Transceiver Electrical Characteristics

Ta=25°C

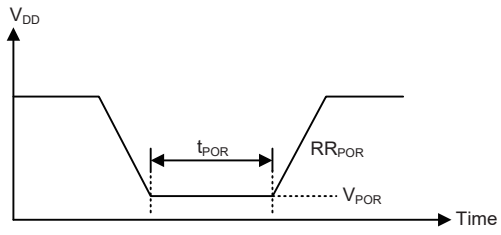
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{CC}	Operating Voltage	—	—	7	—	42	V
I_{CC}	Operating Current	—	V_{CC} = 42V, V_{DD} No Load	—	20	40	μA
V_T	Threshold Voltage	—	—	—	V_{MARK}-5.6	—	V
I_{MC}	Modulate Current	—	R_S = 100Ω	—	15	—	mA
		—	R_S = 47Ω	—	32	—	
V_{IL}	Input Low Voltage for TX Line	5V	—	0	—	1.5	V
		3.3V	—	0	—	0.2V_{DD}	
V_{IH}	Input High Voltage for TX Line	5V	—	3.5	—	5	V
		3.3V	—	0.8V_{DD}	—	V_{DD}	
I_{OL}	Sink Current for RX Line	3.3V	V_{OL} = 0.1V_{DD}	4	8	—	mA
		5V		10	20	—	
I_{OH}	Source Current for RX Line	3.3V	V_{OH} = 0.9V_{DD}	-2	-4	—	mA
		5V		-5	-10	—	
R_{PH}	Pull-high Resistance for TX	—	—	-30%	50	30%	kΩ
LDO							
V_{OUT}	Output Voltage	3.3V	V_{CC} = 7V, I_{LOAD} = 10mA	3.2	3.3	3.4	V
		5V		4.85	5	5.15	
I_{OUT}	Output Current	—	V_{CC} = 10V, ΔV_{OUT} = -3%	60	—	—	mA
			V_{CC} = 7V, ΔV_{OUT} = -3%	30	—	—	
ΔV_{LINE}	Line Regulation	—	7V ≤ V_{IN} ≤ 42V, I_{LOAD} = 1mA	—	—	0.2	%/V

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
TC	Temperature Coefficient	3.3V	Ta = -40°C ~ 85°C, V_{CC} = 7V, I_{LOAD} = 10mA	—	±0.5	±1	mV/°C
		5V		—	±0.75	±1.5	
ΔV_{OUT_RIPPLE}	Output Voltage Ripple	—	V_{CC} = 7V, I_{LOAD} = 10mA	—	—	40	mV
t_{START}	LDO Startup Time	3.3V	V_{CC} = 7V, I_{LOAD} = 1mA, V_{OUT} = 3.3V ± 3%	—	—	10	ms
		5V	V_{CC} = 7V, I_{LOAD} = 1mA, V_{OUT} = 5V ± 3%	—	—	10	ms
I_{OL}	Sink Current for VDD	—	V_{CC} = 5V, V_{OL} = 0.5V	0.8	—	—	mA
LVD							
V_{LVD}	Low Voltage Detection Voltage	—	—	5.0	5.25	5.5	V
TC	Temperature Coefficient ($\Delta V_{LVD}/\Delta Ta$)	—	Ta = -40°C ~ 85°C	—	±0.9	—	mV/°C
V_{DET}	Power up Detection Voltage (V_{CC} Positive-going Threshold Voltage)	—	—	6.2	6.5	6.8	V
Comparator							
A_{OL}	Open Loop Gain	—	—	60	80	—	dB
V_{HYS}	Hysteresis	—	—	—	0.15	—	V
t_{RP}	Response Time	—	—	—	—	5	μs
Constant Current Modulator							
t_{RP}	Response Time	—	No Load	—	—	5	μs

Power-on Reset Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{POR}	V_{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR_{POR}	V_{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t_{POR}	Minimum Time for V_{DD} Stays at V_{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



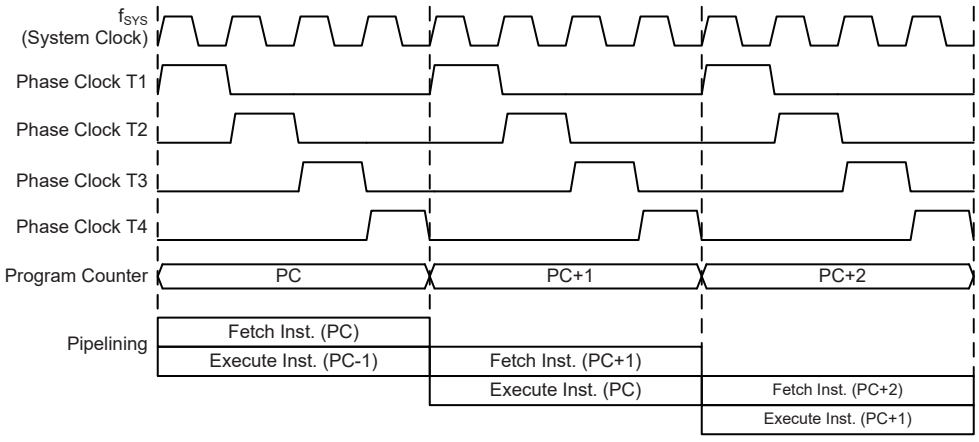
System Architecture

A key factor in the high-performance features of the range of microcontrollers is attributed to their internal system architecture. The device takes advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one cycle with the exceptions of branch or call instructions. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for low-cost, high-volume production for controller applications.

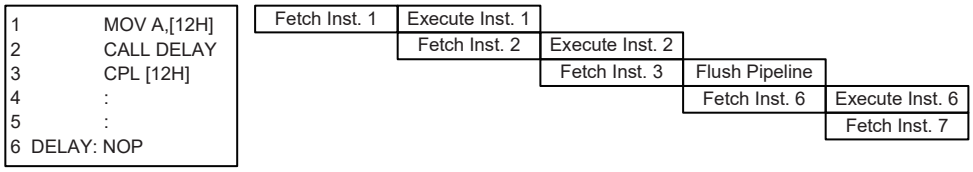
Clocking and Pipelining

The main system clock, derived from either an HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



System Clocking and Pipelining



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demands a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
Program Counter High Byte	**PCL Register**
PC10~PC8	PCL7~PCL0

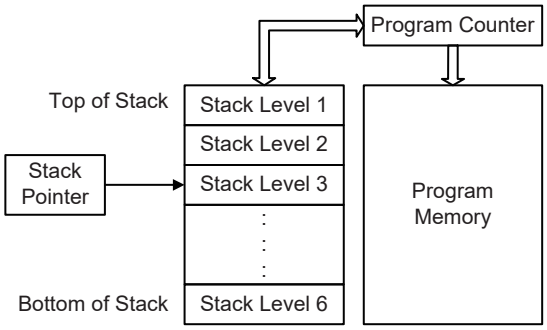
Program Counter

The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly. However, as only this low byte is available for manipulation, the jumps are limited to the present page of memory, that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organised into 6 levels and is neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, and is neither readable nor writeable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching. If the stack is overflow, the first Program Counter save in the stack will be lost.



Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

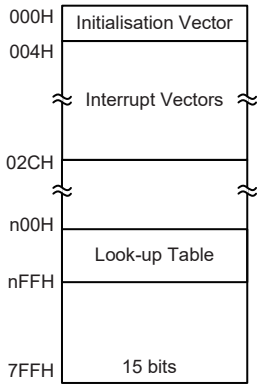
- Arithmetic operations:
  ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA
- Logic operations:
  AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA
- Rotation:
  RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC
- Increment and Decrement:
  INCA, INC, DECA, DEC
- Branch decision:
  JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For this device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of 2K×15 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP and TBHP. These registers define the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the corresponding table read instruction such as “TABRD [m]” or “TABRDL [m]” respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register.

The accompanying diagram illustrates the addressing data flow of the look-up table.

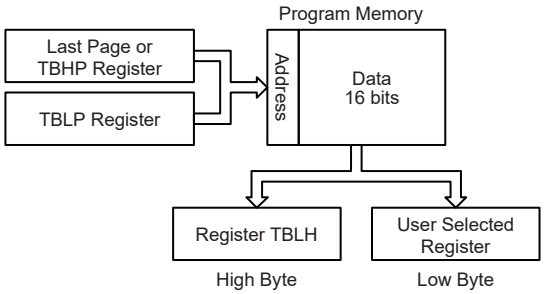


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is "700H" which refers to the start address of the last page within the 2K Program Memory of the microcontroller. The table pointer low byte register is setup here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "706H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the first address specified by TBLP and TBHP if the "TABRD [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRD [m]" instruction is executed.

Because the TBLH register is a read-only register and cannot be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```
tempreg1 db ?      ; temporary register #1
tempreg2 db ?      ; temporary register #2
:
:
mov a,06h          ; initialise low table pointer - note that this address is referenced
mov tblp,a         ; to the last page or the page that tbhp pointed
mov a,07h          ; initialise high table pointer
mov tbhp,a         ; It is not necessary to set tbhp register if executing "tabrdl"
                   ; instruction
:
:
tabrd tempreg1     ; transfers value in table referenced by table pointer data at program
                   ; memory address "706H" transferred to tempreg1 and TBLH
dec tblp           ; reduce value of table pointer by one
tabrd tempreg2     ; transfers value in table referenced by table pointer
                   ; data at program memory address "705H" transferred to
                   ; tempreg2 and TBLH in this example the data "1AH" is
                   ; transferred to tempreg1 and data "0FH" to register tempreg2
:
:
org 700h           ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
```

In Circuit Programming – ICP

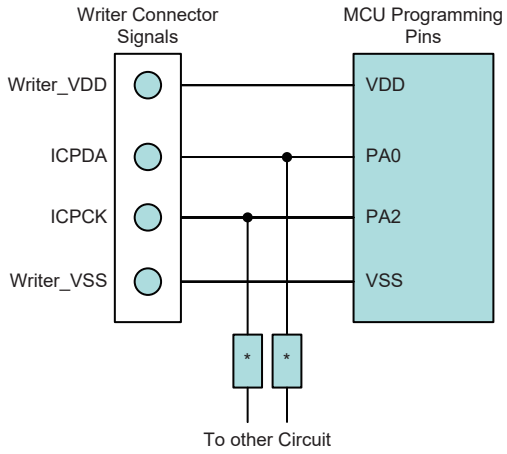
The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. As an additional convenience, a means of programming the microcontroller in-circuit has provided using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

The Flash MCU to Writer Programming Pin correspondence table is as follows:

Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming serial data/address
ICPCK	PA2	Programming clock
VDD	VDD	Power supply
VSS	VSS	Ground

The Program Memory and EEPROM data Memory can both be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device are beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, taking control of the ICPDA and ICPCK pins for data and clock programming purposes. The user must there take care to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

An EV chip exists for the purposes of device emulation. This EV chip device also provides an "On-Chip Debug" function to debug the device during the development process. The EV chip and the actual MCU device are almost functionally compatible except for the "On-Chip Debug" function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip for debugging, other functions which are shared with the OCDSDA and OCDSCK pins

in the actual MCU device will have no effect in the EV chip. However, the two OCDS pins which are pin-shared with the ICP programming pins are still used as the Flash Memory programming pins for ICP. For a more detailed OCDS description, refer to the corresponding document.

e-Link Pins	EV Chip Pins	Pin Description
OCDSDA	OCDSDA	On-chip debug support data/address input/output
OCDSCK	OCDSCK	On-chip debug support clock input
VDD	VDD	Power supply
VSS	VSS	Ground

Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

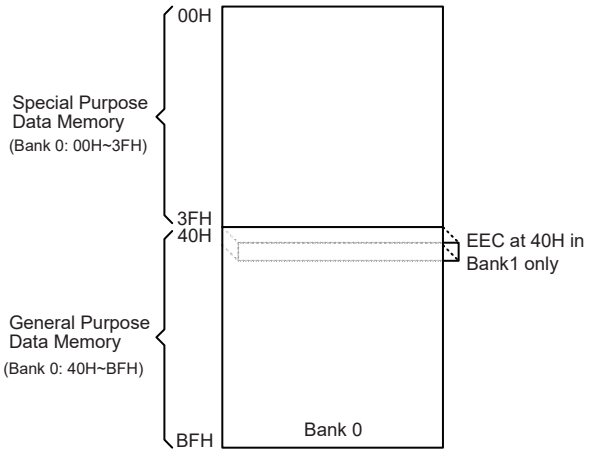
Categorized into two types, the first of these is an area of RAM where special function registers are located. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is reserved for general purpose use. All locations within this area are read and write accessible under program control.

Structure

The Data Memory is subdivided into two banks, all of which are implemented in 8-bit wide Memory. The Special Purpose Data Memory registers are accessible in Bank 0, with the exception of the EEC register at address 40H, which is only accessible in Bank 1. Switching between the different Data Memory banks is achieved by properly setting the Bank Pointer to correct value. The start address of the Data Memory is the address 00H.

Special Purpose Data Memory	General Purpose Data Memory	
Available Banks	Capacity	Bank: Address
0: 00H~3FH 1: 40H (EEC only)	128×8	0: 40H~BFH

Data Memory Summary



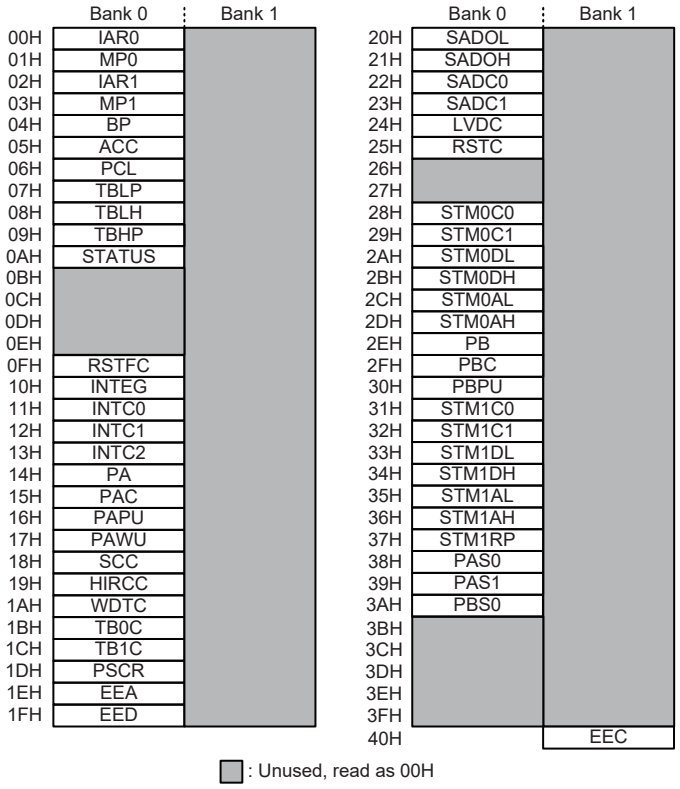
Data Memory Structure

General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programing for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.



Special Purpose Data Memory

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional sections, however several registers require a separate description in this section.

Indirect Addressing Registers – IAR0, IAR1

The Indirect Addressing Registers, IAR0 and IAR1, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0 and IAR1 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0 or MP1. Acting as a pair, IAR0 and MP0 can together access data only from Bank 0 while the IAR1 register together with the MP1 register pair can access data from any Data Memory Bank. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers will return a result of "00H" and writing to the registers will result in no operation.

Memory Pointers – MP0, MP1

Two Memory Pointers, known as MP0 and MP1 are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Bank 0, while MP1 and IAR1 are used to access data from all banks according to the BP register. Direct Addressing can be used in Bank 0, all other banks must be addressed indirectly using MP1 and IAR1.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

Indirect Addressing Program Example

```
data .section ´data´
adres1   db ?
adres2   db ?
adres3   db ?
adres4   db ?
block    db ?
code .section at 0 ´code´
org 00h
start:
     mov a, 04h              ; setup size of block
     mov block, a
     mov a, offset adres1    ; Accumulator loaded with first RAM address
     mov mp0, a              ; setup memory pointer with first RAM address
loop:
     clr IAR0                ; clear the data at address defined by MP0
     inc mp0                 ; increment memory pointer
     sdz block               ; check if last memory location has been cleared
     jmp loop
continue:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

Bank Pointer – BP

For this device, the Data Memory is divided into two banks, Bank 0 and Bank 1. Selecting the required Data Memory area is achieved using the Bank Pointer. Bit 0 of the Bank Pointer is used to select Data Memory Banks 0~1.

The Data Memory is initialised to Bank 0 after a reset, except for a WDT time-out reset in the SLEEP/IDLE Mode, in which case, the Data Memory bank remains unaffected. It should be noted that the Special Function Data Memory is not affected by the bank selection, which means that the Special Function Registers can be accessed from within any bank. Directly addressing the Data Memory will always result in Bank 0 being accessed irrespective of the value of the Bank Pointer. Accessing data from Bank 1 must be implemented using Indirect Addressing.

BP Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	DMBP0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **DMBP0**: Select Data Memory Banks
0: Bank 0
1: Bank 1

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user-defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBHP, TBLH

These three special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP and TBHP are the table pointers and indicate the location where the table data is located. Their value must be setup before any table read commands are executed. Their value can be changed, for example using the "INC" or "DEC" instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Status Register – STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the "CLR WDT" or "HALT" instruction. The PDF flag is affected only by executing the "HALT" or "CLR WDT" instruction or during a system power-up.

The Z, OV, AC and C flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
- TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

STATUS Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	TO	PDF	OV	Z	AC	C
R/W	—	—	R	R	R/W	R/W	R/W	R/W
POR	—	—	0	0	x	x	x	x

"x": unknown

Bit 7~6 Unimplemented, read as "0"

Bit 5 **TO**: Watchdog Time-Out Flag
0: After power up or executing the "CLR WDT" or "HALT" instruction
1: A watchdog time-out occurred.

Bit 4 **PDF**: Power Down Flag
0: After power up or executing the "CLR WDT" instruction
1: By executing the "HALT" instruction

Bit 3 **OV**: Overflow Flag
0: No overflow
1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa.

Bit 2 **Z**: Zero Flag
0: The result of an arithmetic or logical operation is not zero
1: The result of an arithmetic or logical operation is zero

Bit 1 **AC**: Auxiliary flag
0: No auxiliary carry
1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction

Bit 0 **C**: Carry Flag
0: No carry-out
1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation

The "C" flag is also affected by a rotate through carry instruction.

EEPROM Data Memory

This device contains an area of internal EEPROM Data Memory. EEPROM is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 64×8 bits for the device. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in single byte operations using an address and a data register in Bank 0 and a single control register in Bank 1.

EEPROM Registers

Three registers control the overall operation of the internal EEPROM Data Memory. These are the address register, EEA, the data register, EED and a single control register, EEC. As both the EEA and EED registers are located in Bank 0, they can be directly accessed in the same was as any other Special Function Register. The EEC register however, being located in Bank 1, can be read from or written to indirectly using the MP1 Memory Pointer and Indirect Addressing Register, IAR1. Because the EEC control register is located at address 40H in Bank 1, the MP1 Memory Pointer must first be set to the value 40H and the Bank Pointer register BP set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEA	—	—	EEA5	EEA4	EEA3	EEA2	EEA1	EEA0
EED	D7	D6	D5	D4	D3	D2	D1	D0
EEC	—	—	—	—	WREN	WR	RDEN	RD

EEPROM Registers List

EEA Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	EEA5	EEA4	EEA3	EEA2	EEA1	EEA0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5~0 **EEA5~EEA0**: Data EEPROM address bit 5 ~ bit 0

EED Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Data EEPROM data bit 7 ~ bit 0

EEC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	WREN	WR	RDEN	RD
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3 **WREN**: Data EEPROM Write Enable
0: Disable
1: Enable
This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations.

Bit 2 **WR**: EEPROM Write Control
0: Write cycle has finished
1: Activate a write cycle
This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.

Bit 1 **RDEN**: Data EEPROM Read Enable
0: Disable
1: Enable
This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.

Bit 0 **RD**: EEPROM Read Control
0: Read cycle has finished
1: Activate a read cycle
This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN bit has not first been set high.

Note: The WREN, WR, RDEN and RD cannot be set high at the same time in one instruction. The WR and RD cannot be set high at the same time.

Reading Data from the EEPROM

To read data from the EEPROM, the read enable bit, RDEN, in the EEC register must first be set high to enable the read function. The EEPROM address of the data to be read must then be placed in the EEA register. If the RD bit in the EEC register is now set high, a read cycle will be initiated. Setting the RD bit high will not initiate a read operation if the RDEN bit has not been set. When the read cycle terminates, the RD bit will be automatically cleared to zero, after which the data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

Writing Data to the EEPROM

The EEPROM address of the data to be written must first be placed in the EEA register and the data placed in the EED register. To write data to the EEPROM, the write enable bit, WREN, in the EEC register must first be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle. These two instructions must be executed consecutively. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set again after the write cycle has started. Note that setting the WR bit high will not initiate a write cycle if the WREN bit has not been set. As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended.

Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Bank Pointer, BP, will be reset to zero, which means that Data Memory Bank 0 will be selected. As the EEPROM control register is located in Bank 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

EEPROM Interrupt

The EEPROM write interrupt is generated when an EEPROM write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. When an EEPROM write cycle ends, the DEF request flag will be set. If the global and EEPROM interrupts are enabled and the stack is not full, a jump to the associated EEPROM Interrupt vector will take place. When the EEPROM interrupt is serviced, the EEPROM interrupt flag DEF will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts. More details can be obtained in the Interrupt section.

Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Bank Pointer could be normally cleared to zero as this would inhibit access to Bank 1 where the EEPROM control register exist. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. The global interrupt bit EMI should also be cleared before a write cycle is executed and then re-enabled after the write cycle starts. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read or write operation is totally complete. Otherwise, the EEPROM read or write operation will fail.

Programming Examples

Reading data from the EEPROM – polling method

```
MOV  A, EEPROM_ADRES          ; user defined address
MOV  EEA, A
MOV  A, 040H                  ; setup memory pointer MP1
MOV  MP1, A                   ; MP1 points to EEC register
MOV  A, 01H                   ; setup Bank pointer
MOV  BP, A
SET  IAR1.1                   ; set RDEN bit, enable read operations
SET  IAR1.0                   ; start Read Cycle - set RD bit
BACK:
SZ   IAR1.0                   ; check for read cycle end
JMP  BACK
CLR  IAR1                     ; disable EEPROM read
CLR  BP
MOV  A, EED                   ; move read data to register
MOV  READ_DATA, A
```

Writing Data to the EEPROM – polling method

```
MOV  A, EEPROM_ADRES          ; user defined address
MOV  EEA, A
MOV  A, EEPROM_DATA           ; user defined data
MOV  EED, A
MOV  A, 040H                  ; setup memory pointer MP1
MOV  MP1, A                   ; MP1 points to EEC register
MOV  A, 01H                   ; setup Bank pointer
MOV  BP, A
CLR  EMI
SET  IAR1.3                   ; set WREN bit, enable write operations
SET  IAR1.2                   ; start Write Cycle - set WR bit - executed immediately
                              ; after set WREN bit
SET  EMI
BACK:
SZ   IAR1.2                   ; check for write cycle end
JMP  BACK
CLR  IAR1                     ; disable EEPROM write
CLR  BP
```

Oscillators

Various oscillator options offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through relevant control registers.

Oscillator Overview

In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer and Time Base Interrupts. Two fully integrated internal oscillators, requiring no external components, are provided to form a wide range of both fast and slow system oscillators. All oscillator options are selected through the registers. The higher frequency oscillators provide higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillators. With the capability of dynamically switching between fast and slow system clock, the device have the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

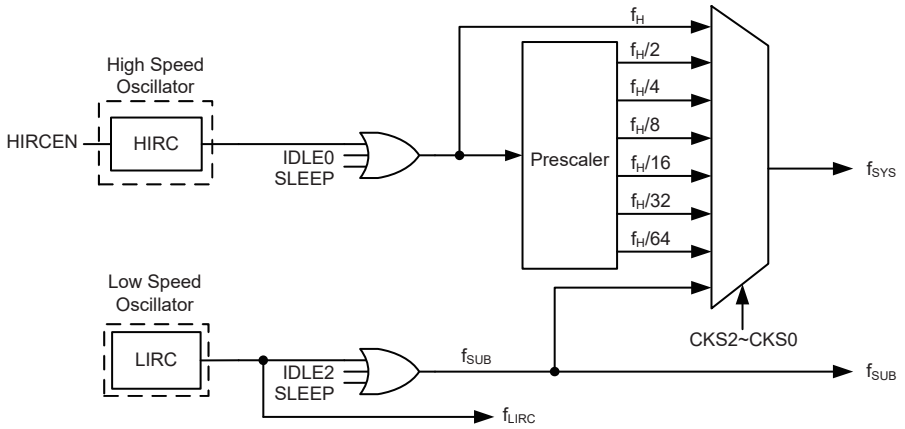
Type	Name	Freq.
Internal High Speed RC	HIRC	2/4MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two methods of generating the system clock, a high speed oscillator and a low speed oscillator. The high speed oscillator is the internal 2/4MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and the system clock can be dynamically selected.

The actual source clock used for the low speed oscillators is chosen via registers. The frequency of the slow speed or high speed system clock is determined using the CKS2~CKS0 bits in the SCC register. Note that two oscillator selections must be made namely one high speed and one low speed system oscillators. It is not possible to choose a no-oscillator selection for either the high or low speed oscillator.



System Clock Configurations

Internal RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has a fixed frequency of 2/4MHz. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised. As a result, at a power supply of 3V or 5V and at a temperature of 25°C degrees, the selected trimmed oscillation frequency will have a tolerance within 1%.

Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is a fully integrated RC oscillator with a typical frequency of 32kHz at 5V, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised. As a result, at a power supply of 5V and at a temperature of 25˚C degrees, the fixed oscillation frequency of 32kHz will have a tolerance within 10%.

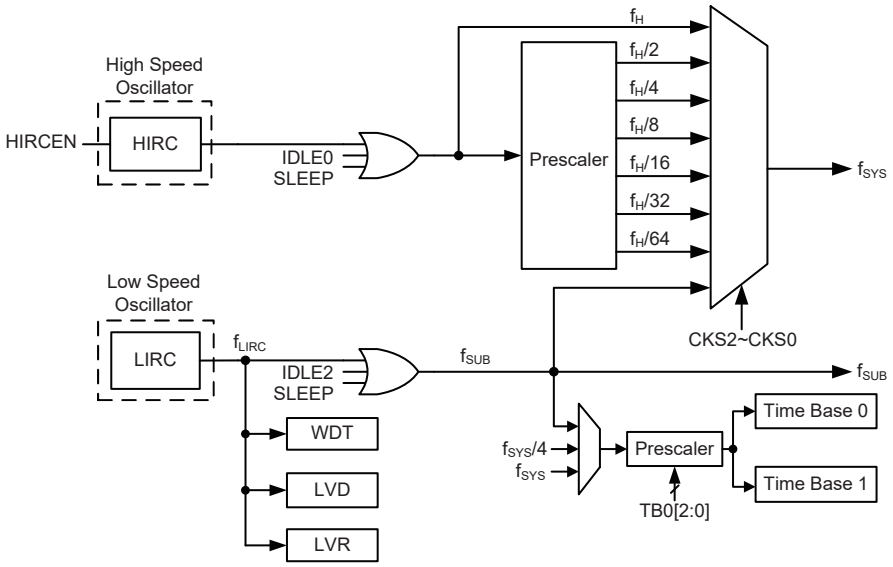
Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice versa, lower speed clocks reduce current consumption. As both high and low speed clock sources are provided the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock selections using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from either a high frequency, f_H, or low frequency, f_{SUB}, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock is sourced from the HIRC oscillator. The low speed system clock source can be sourced from the internal clock f_{SUB}. If f_{SUB} is selected then it can be sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2$~$f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H, the high speed oscillator can be stopped to conserve the power or continue to oscillate to provide the clock source, f_H~$f_H/64$, for peripheral circuit to use, which is determined by configuring the corresponding high speed oscillator enable control bit.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f_{SYS}	f_H	f_{SUB}	f_{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f_H~$f_H/64$	On	On	On
SLOW	On	x	x	111	f_{SUB}	On/Off (1)	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On/Off(2)

"x": don't care

Note: 1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f_{LIRC} clock can be switched on or off which is controlled by the WDT function being enabled or disabled in the SLEEP mode.

FAST Mode

As the name suggests this is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source will come from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{SUB}. The f_{SUB} clock is derived from the LIRC oscillator.

SLEEP Mode

The SLEEP Mode is entered when an HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped, and the f_{SUB} clock to peripheral will be stopped too. However the f_{LIRC} clock can continue to operate if the WDT function is enabled.

IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN

System Operating Mode Control Registers List

SCC Register

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection
000: f_H
001: $f_H/2$
010: $f_H/4$
011: $f_H/8$
100: $f_H/16$
101: $f_H/32$
110: $f_H/64$
111: f_{SUB}
These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB}, a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as "0"

Bit 1 **FHIDEN**: High Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

Bit 0 **FSIDEN**: Low Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

HIRCC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN
R/W	—	—	—	—	R/W	R/W	R	R/W
POR	—	—	—	—	0	0	0	1

Bit 7~4 Unimplemented, read as "0"

Bit 3~2 **HIRC1~HIRC0**: HIRC Frequency selection
00: 2MHz
01: 4MHz
10: Reserved
11: 2MHz
When the HIRC oscillator is enabled or the HIRC frequency selection is changed by application program, the clock frequency will automatically be changed after the HIRCF flag is set to 1.

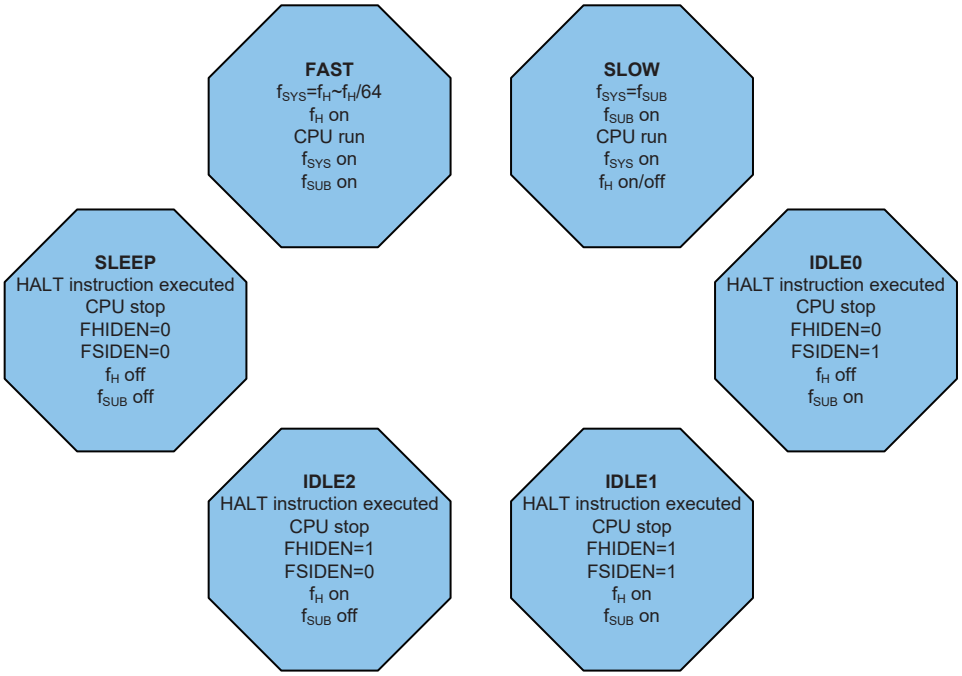
Bit 1 **HIRCF**: HIRC oscillator stable flag
0: HIRC unstable
1: HIRC stable
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator or the HIRC frequency selection is changed by application program, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
0: Disable
1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

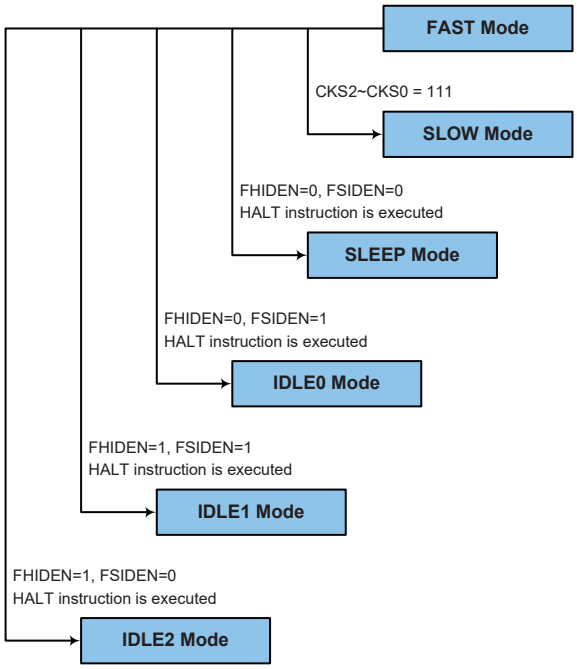
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Modes to the SLEEP/IDLE Modes is executed via the HALT instruction. When an HALT instruction is executed, whether the device enters the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to "111" in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

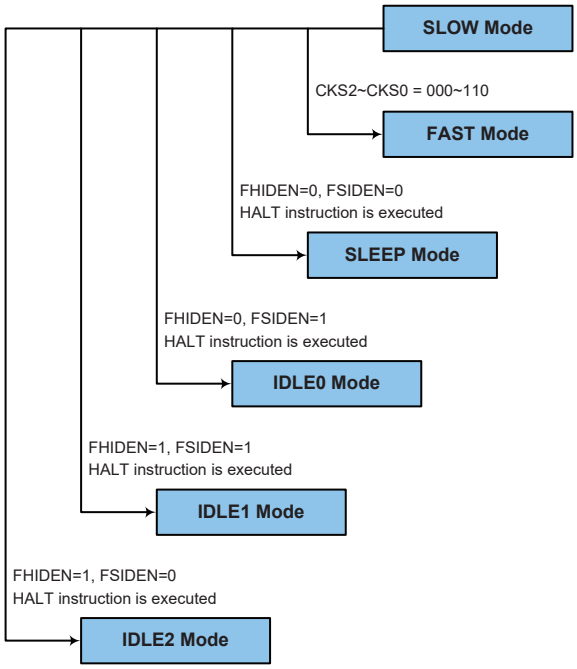
The SLOW Mode is sourced from the LIRC oscillator and therefore requires this oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from f_{SUB}. When system clock is switched back to the FAST mode from f_{SUB}, the CKS2~CKS0 bits should be set to "000"~"110" and then the system clock will respectively be switched to f_H~f_H/64.

However, if f_H is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the relevant characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "0". In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT is enabled. If the WDT is disabled then WDT will be cleared and stopped.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "0" and the FSIDEN bit in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the "HALT" instruction, but the f_{SUB} clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT is enabled. If the WDT is disabled then WDT will be cleared and stopped.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE1 Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on but the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT is enabled. If the WDT is disabled then WDT will be cleared and stopped.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "1" and the FSIDEN bit in the SCC register equal to "0". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT is enabled. If the WDT is disabled then WDT will be cleared and stopped.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps except in the IDLE1 and IDLE2 Mode, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to devices which have different package types, as there may be unbonbed pins. These must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs. Also note that additional standby current will also be required if the LIRC oscillator has enabled.

In the IDLE1 and IDLE2 Mode the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stablise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- An external reset
- A system interrupt
- A WDT overflow

If the system is woken up by an external reset, the device will experience a full system reset. When the device executes the “HALT” instruction, the PDF flag will be set to 1. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set to 1. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be setup using the PAWU register to permit a negative transition on the pin to wake up the system. When a Port A pin wake-up occurs, the program will resume execution at the instruction following the “HALT” instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the “HALT” instruction. In this situation, the interrupt which woke up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC}, which is supplied by the LIRC oscillator. The LIRC internal oscillator has an approximate frequency of 32kHz and this specified internal clock period can vary with V_{DD}, temperature and process variations.The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer timeouts, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required timeout period as well as the enable/disable and reset MCU operation.

WDTC Register

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function software control
10101: Disable
01010: Enable
Others: Reset MCU
When these bits are changed by the environmental noise or software setting to reset the microcontroller, the reset operation will be activated after a delay time, t_{SRESET}, and the WRF bit in the RSTFC register will be set high.

Bit 2~0 **WS2~WS0**: WDT time-out period selection
000: $2^8/f_{LIRC}$
001: $2^{10}/f_{LIRC}$
010: $2^{12}/f_{LIRC}$
011: $2^{14}/f_{LIRC}$
100: $2^{15}/f_{LIRC}$
101: $2^{16}/f_{LIRC}$
110: $2^{17}/f_{LIRC}$
111: $2^{18}/f_{LIRC}$
These three bits determine the division ratio of the watchdog timer source clock, which in turn determines the time-out period.

RSTFC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	RSTF	LVRF	—	WRF
R/W	—	—	—	—	R/W	R/W	—	R/W
POR	—	—	—	—	0	x	—	0

"x": unknown

Bit 7~4 Unimplemented, read as "0"

Bit 3 **RSTF**: Reset control register software reset flag
Described elsewhere

Bit 2 **LVRF**: LVR function reset flag
Described elsewhere

Bit 1 Unimplemented, read as "0"

Bit 0 **WRF**: WDT Control Register Software Reset Flag
0: Not occur
1: Occurred
This bit is set high by the WDT Control register software reset and cleared by the application program. Note that this bit can only be cleared to zero by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instructions. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, these clear instructions will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer the enable/disable control and reset control of the Watchdog Timer. The WDT function will be disabled when the WE4~WE0 bits are set to a value of 10101B while the WDT function will be enabled if the WE4~WE0 bits are equal to 01010B. If the WE4~WE0 bits are set to any other values, other than 01010B and 10101B, it will reset the device after a delay time, t_{SRESET}. After power on these bits will have a value of 01010B.

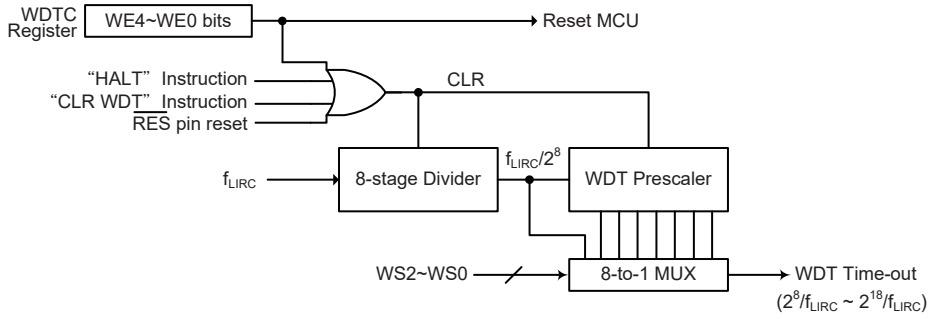
WE4 ~ WE0 Bits	WDT Function
10101B	Disable
01010B	Enable
Any other values	Reset MCU

Watchdog Timer Enable/Disable Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the status register will be set and only the Program Counter and Stack Pointer will be reset. Four methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDT reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction. The last is an external hardware reset, which means a low level on the external reset pin if the external reset pin exists by the RSTC register.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single "CLR WDT" instruction to clear the WDT.

The maximum time out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 seconds for the 2^{18} division ratio, and a minimum timeout of 8ms for the 2^8 division ration.



Watchdog Timer

Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

In addition to the power-on reset, situations may arise where it is necessary to forcefully apply a reset condition when the microcontroller is already running, the $\overline{RES}$ line is forcefully pulled low. In such a case, known as a normal operation reset, some of the microcontroller registers remain unchanged allowing the microcontroller to preceed with normal operation after the reset line is allowed to return high.

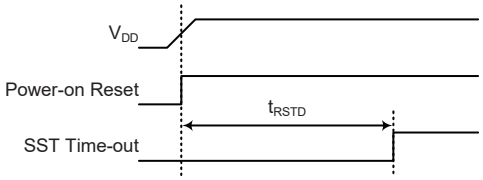
The Watchdog Timer overflow is one of many reset types and will reset the microcontroller. Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset, similar to the $\overline{RES}$ reset is implemented in situations where the power supply voltage falls below a certain threshold. All types of reset operations result in different register conditions being setup.

Reset Functions

There are several ways in which a microcontroller reset can occur, through events occurring both internally and externally.

Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all I/O ports will be first set to inputs.

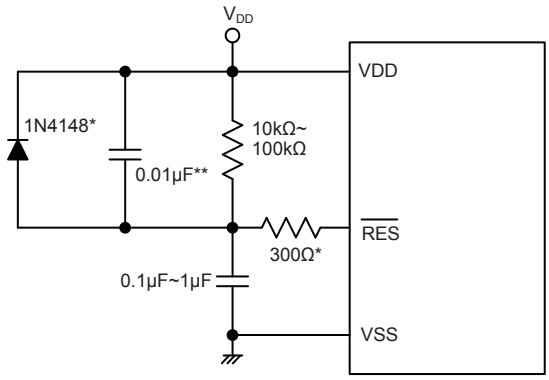


Power-On Reset Timing Chart

$\overline{RES}$ Pin Reset

As the reset pin is shared with I/O pins, the reset function must be selected using a control register, RSTC. Although the microcontroller has an internal RC reset function, if the V_{DD} power supply rise time is not fast enough or does not stabilise quickly at power-on, the internal reset function may be incapable of providing proper reset operation. For this reason it is recommended that an external RC network is connected to the $\overline{RES}$ pin, whose additional time delay will ensure that the $\overline{RES}$ pin remains low for an extended period to allow the power supply to stabilise. During this time delay, normal operation of the microcontroller will be inhibited. After the $\overline{RES}$ line reaches a certain voltage value, the reset delay time, t_{RSTD}, is invoked to provide an extea delay time after which the microcontroller will begin normal operation. The abbreviation SST in the figures stands for System Start-up Time. For most applications a resistor connected between VDD and the $\overline{RES}$ line and a

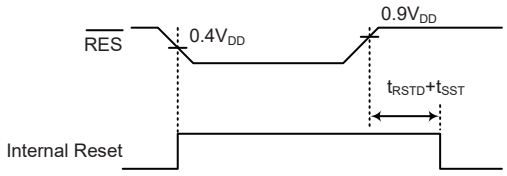
capacitor connected betweeb VSS and the $\overline{RES}$ pin will provide a suitable external reset circuit. Any wiring connected to the $\overline{RES}$ pin should be kept as short as possible to minimise any stray noise interference. For applications that operate within an environment where more noise is present the Enhanced Reset Circuit shown is recommended.



Note: "*" It is recommended that this component is added for added ESD protection.
"**" It is recommended that this component is added in environments where power line noise is significant.

External $\overline{RES}$ Circuit

Pulling the $\overline{RES}$ pin low using external hardware will also execute a device reset. In this case, as in the case of other resets, the Progran Counter will reset to zero and program execution initiated from this point.



$\overline{RES}$ Reset Timing Chart

There is an internal reset control register, RSTC, which is used to select the external $\overline{RES}$ pin function and provide a reset when the device operates abnormally due to the environmental noise interference. If the content of the RSTC register is set to any value other than 01010101B or 10101010B, it will reset the device after a delay time, t_{SRESET}. After power on the register will have a value of 01010101B.

RSTC7 ~ RSTC0 Bits	Reset Function
01010101B	PB4
10101010B	$\overline{RES}$
Any other value	Reset MCU

Internal Reset Function Control

- **RSTC Register**

Bit	7	6	5	4	3	2	1	0
Name	RSTC7	RSTC6	RSTC5	RSTC4	RSTC3	RSTC2	RSTC1	RSTC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	1	0	1

Bit 7~0 **RSTC7~RSTC0**: Reset function control
01010101: PB4
10101010: $\overline{\text{RES}}$ pin
Other values: Reset MCU
If these bits are changed due to adverse environmental conditions, the microcontroller will be reset. The reset operation will be activated after a delay time, t_{SRESET}, and the RSTF bit in the RSTFC register will be set to 1.
All resets will reset this register to POR value except the WDT time out hardware warm reset. Note that if the register is set to 10101010 to select the $\overline{\text{RES}}$ pin, this configuration has higher priority than other related pin-shared controls.

- **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	RSTF	LVRF	—	WRF
R/W	—	—	—	—	R/W	R/W	—	R/W
POR	—	—	—	—	0	x	—	0

"x": unknown

Bit 7~4 Unimplemented, read as "0"

Bit 3 **RSTF**: Reset control register software reset flag
0: Not occurred
1: Occurred
This bit is set to 1 by the RSTC control register software reset and cleared by the application program. Note that this bit can only be cleared to 0 by the application program.

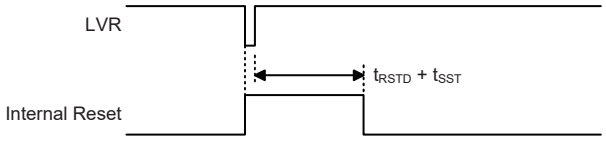
Bit 2 **LVRF**: LVR function reset flag
Described elsewhere

Bit 1 Unimplemented, read as "0"

Bit 0 **WRF**: WDT control register software reset flag
Described elsewhere

Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device. The LVR function is always enabled with a specific LVR voltage V_{LVR}. If the supply voltage of the device drops to within a range of 0.9V~V_{LVR} such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set high. For a valid LVR signal, a low supply voltage, i.e., a voltage in the range between 0.9V~V_{LVR} must exist for a time greater than that specified by t_{LVR} in the LVD/LVR Electrical Characteristics. If the low supply voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. The actual V_{LVR} value is fixed at 2.1V. Note that the LVR function will be automatically disabled when the device enters the IDLE/SLEEP mode.



Low Voltage Reset Timing Chart

- **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	RSTF	LVRF	—	WRF
R/W	—	—	—	—	R/W	R/W	—	R/W
POR	—	—	—	—	0	x	—	0

"x": unknown

Bit 7~4 Unimplemented, read as "0"

Bit 3 **RSTF**: Reset control register software reset flag
Described elsewhere

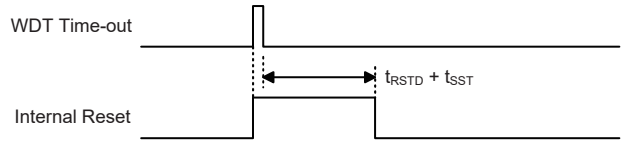
Bit 2 **LVRF**: LVR function reset flag
0: Not occur
1: Occurred
This bit is set high when a specific Low Voltage Reset situation condition occurs. This bit can only be cleared to zero by the application program.

Bit 1 Unimplemented, read as "0"

Bit 0 **WRF**: WDT Control register software reset flag
Described elsewhere

Watchdog Time-out Reset during Normal Operation

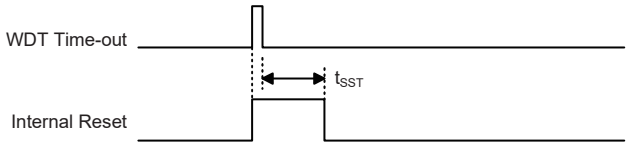
The Watchdog time-out Reset during normal operation is the same as hardware low voltage reset except that the Watchdog time-out flag TO will be set high.



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to zero and the TO flag will be set high. Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during Sleep or IDLE Mode Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	$\overline{RES}$ or LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

"u" stands for unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Modules	Timer Modules will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers. Note that where more than one package type exists the table will reflect the situation for the larger package type.

Register	Reset (Power On)	$\overline{RES}$ Reset (Normal Operation)	LVR Reset (Normal Operation)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
MP0	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
IAR1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
MP1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
BP	---- ---0	---- ---0	---- ---0	---- ---0	---- ---u
ACC	xxxx xxxx	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	-xxx xxxx	-xxx xxxx	-uuu uuuu	-uuu uuuu	-uuu uuuu
TBHP	---- -xxx	---- -xxx	---- -uuu	---- -uuu	---- -uuu
STATUS	--00 xxxx	--uu uuuu	--uu uuuu	--1u uuuu	--11 uuuu
RSTFC	---- 0x-0	---- uu-u	---- u1-u	---- uu-u	---- uu-u
INTEG	---- 0000	---- 0000	---- 0000	---- 0000	---- uuuu
INTC0	-000 0000	-000 0000	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
INTC2	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
PA	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAPU	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
PAWU	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
SCC	000- --00	000- --00	000- --00	000- --00	uuu- --uu
HIRCC	---- 0001	---- 0001	---- 0001	---- 0001	---- uuuu
WDTC	0101 0011	0101 0011	0101 0011	0101 0011	uuuu uuuu
TB0C	0--- -000	0--- -000	0--- -000	0--- -000	u--- -uuu
TB1C	0--- -000	0--- -000	0--- -000	0--- -000	u--- -uuu

Register	Reset (Power On)	$\overline{\text{RES}}$ Reset (Normal Operation)	LVR Reset (Normal Operation)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
PSCR	---- --00	---- --00	---- --00	---- --00	---- --uu
EEA	--00 0000	--00 0000	--00 0000	--00 0000	--uu uuuu
EED	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
SADOL	xxxx ----	xxxx ----	xxxx ----	xxxx ----	uuuu ---- (ADRFS=0)
					uuuu uuuu (ADRFS=1)
SADOH	xxxx xxxx	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu (ADRFS=0)
					---- uuuu (ADRFS=1)
SADC0	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
LVDC	--00 0000	--00 0000	--00 0000	--00 0000	--uu uuuu
RSTC	0101 0101	0101 0101	0101 0101	0101 0101	uuuu uuuu
STM0C0	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM0C1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM0DL	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM0DH	---- --00	---- --00	---- --00	---- --00	---- --uu
STM0AL	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM0AH	---- --00	---- --00	---- --00	---- --00	---- --uu
PB	-111 1111	-111 1111	-111 1111	-111 1111	-uuu uuuu
PBC	-101 1111	-101 1111	-101 1111	-101 1111	-uuu uuuu
PBPU	-000 0000	-000 0000	-000 0000	-000 0000	-uuu uuuu
STM1C0	0000 0---	0000 0---	0000 0---	0000 0---	uuuu u---
STM1C1	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM1DL	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM1DH	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM1AL	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM1AH	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
STM1PR	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
PAS0	00-- 00--	00-- 00--	00-- 00--	00-- 00--	uu-- uu--
PAS1	0000 00--	0000 00--	0000 00--	0000 00--	uuuu uu--
PBS0	0000 0000	0000 0000	0000 0000	0000 0000	uuuu uuuu
EEC	---- 0000	---- 0000	---- 0000	---- 0000	---- uuuu

Note: “u” stands for unchanged
“x” stands for unknown
“-” stands for unimplemented

Input/Output Ports

The microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA~PB. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction "MOV A, [m]", where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
PAC	PAC7	PAC5	PAC5	PAC4	PAC3	PAC2	PAC1	PAC0
PAPU	PAPU7	PAPU4	PAPU5	PAPU4	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
PB	—	PB6	PB5	PB4	PB3	PB2	PB1	PB0
PBC	—	PBC6	PBC5	PBC4	PBC3	PBC2	PBC1	PBC0
PBPU	—	PBPU6	PBPU5	PBPU4	PBPU3	PBPU2	PBPU1	PBPU0

"—": unimplemented

I/O Logic Function Registers List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as an input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using the PAPU~PBPU registers, and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

PAPU Register

Bit	7	6	5	4	3	2	1	0
Name	PAPU7	PAPU4	PAPU5	PAPU4	PAPU3	PAPU2	PAPU1	PAPU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **PAPU7~PAPU0**: I/O Port PA7~PA0 Pin Pull-high Function Control
0: Disable
1: Enable

PBPU Register

Bit	7	6	5	4	3	2	1	0
Name	—	PBPU6	PBPU5	PBPU4	PBPU3	PBPU2	PBPU1	PBPU0
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6~5 **PBPU6~PBPU5**: Un-bonded I/O Line PB6~PB5 Pull-high Controll
0: Disable
1: Enable

Note: The PB5 and PB6 lines of the MCU are internally connceted with the TX and RX lines of the power line data transceiver. However their pull-high functions can still be controlled by these bits.

Bit 4~0 **PBPU4~PBPU0**: I/O Port PB4~PB0 Pin Pull-high Control
0: Disable
1: Enable

Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin-shared functional pin is selected as general purpose input/output and the MCU enters the SLEEP/IDLE mode.

PAWU Register

Bit	7	6	5	4	3	2	1	0
Name	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **PAWU7~PAWU0**: Port A Pin Wake-up Control
0: Disable
1: Enable

I/O Port Control Registers

Each I/O port has its own control register which controls the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

PAC Register

Bit	7	6	5	4	3	2	1	0
Name	PAC7	PAC5	PAC5	PAC4	PAC3	PAC2	PAC1	PAC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	1	1	1	1	1

Bit 7~0 **PAC7~PAC0**: I/O Port PA7~PA0 Pin Type Selection
0: Output
1: Input

PBC Register

Bit	7	6	5	4	3	2	1	0
Name	—	PBC6	PBC5	PBC4	PBC3	PBC2	PBC1	PBC0
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	1	0	1	1	1	1	1

Bit 7 Unimplemented, read as "0"

Bit 6 **PBC6**: Un-bonded PB6 I/O Line Type
As the PB6 line is internally connected with the RX line of the power line data transceiver, this bit should be fixed at "1" to select the input type.

Bit 5 **PBC5**: Un-bonded PB5 I/O Line Type
As the PB5 line is internally connected with the TX line of the power line data transceiver, this bit should be fixed at "0" to select the output type.

Bit 4~0 **PBC4~PBC0**: I/O Port PB4~PB0 Input/Output Control
0: Output
1: Input

Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes Port "x" output function Selection register "n", labeled as PxSn, which can select the desired functions of the multi-function pin-shared pins.

When the pin-shared input function is selected to be used, the corresponding input and output functions selection should be properly managed. However, if the external interrupt function is selected to be used, the relevant output pin-shared function should be selected as an I/O function and the interrupt input signal should be selected.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, special point must be noted for some digital input pins, such as INT, STCKn, etc, which share the same pin-shared control configuration with their

corresponding general purpose I/O functions when setting the relevant functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be setup as input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PAS0	PAS07	PAS06	—	—	PAS03	PAS02	—	—
PAS1	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	—	—
PBS0	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00

Pin-shared Function Selection Registers List

- **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS07	PAS06	—	—	PAS03	PAS02	—	—
R/W	R/W	R/W	—	—	R/W	R/W	—	—
POR	0	0	—	—	0	0	—	—

Bit 7~6 **PAS07~PAS06**: PA3 pin-shared function selection
00/10/11: PA3/STCK0
01: AN4

Bit 5~4 Unimplemented, read as "0"

Bit 3~2 **PAS03~PAS02**: PA1 pin-shared function selection
00/11: PA1
01: STP0
10: VREF

Bit 1~0 Unimplemented, read as "0"

- **PAS1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	—	—
R/W	R/W	R/W	R/W	R/W	R/W	R/W	—	—
POR	0	0	0	0	0	0	—	—

Bit 7~6 **PAS17~PAS16**: PA7 pin-shared function selection
00/10/11: PA7
01: AN7

Bit 5~4 **PAS15~PAS14**: PA6 pin-shared function selection
00/10/11: PA6
01: AN6

Bit 3~2 **PAS13~PAS12**: PA5 pin-shared function selection
00/10/11: PA5/STP0I
01: AN5

Bit 1~0 Unimplemented, read as "0"

- **PBS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PBS07~PBS06**: PB3 pin-shared function selection
00/10/11: PB3
01: AN3

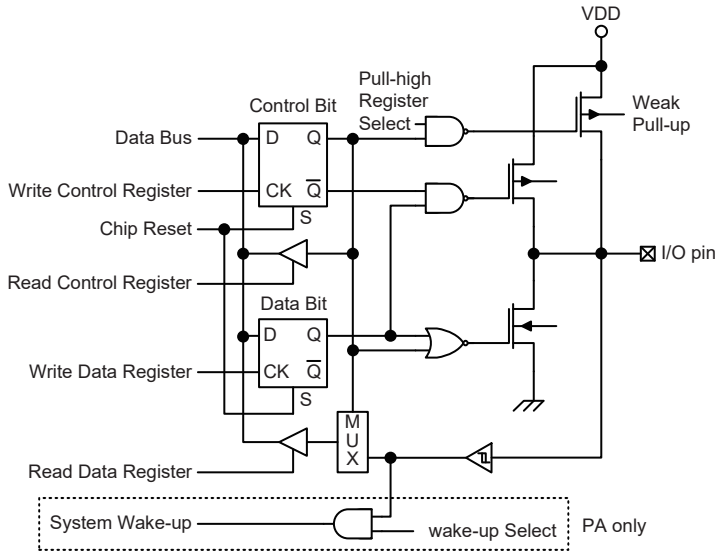
Bit 5~4 **PBS05~PBS04**: PB2 pin-shared function selection
00/10/11: PB2/STP1I
01: AN2

Bit 3~2 **PBS03~PBS02**: PB1 pin-shared function selection
00/10/11: PB1/STCK1
01: AN1

Bit 1~0 **PBS01~PBS00**: PB0 pin-shared function selection
00/11: PB0
01: STP1
10: AN0

I/O Pin Structures

The accompanying diagram illustrates the internal structures of the I/O logic function. As the exact logical construction of the I/O pin will differ from this diagram, it is supplied as a guide only to assist with the functional understanding of the logic function I/O pins. The wide range of pin-shared structures does not permit all types to be shown.



Logic Function Input/Output Structure

Programming Considerations

Within the user program, one of the things first to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set to high. This means that all I/O pins will be defaulted to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.

Timer Modules – TM

One of the most fundamental functions in any microcontroller devices is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, generally abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two interrupts. The addition of input and output pins for each TM ensures that users are provided with timing units with a wide and flexible range of features.

Introduction

The device contains two TMs and each individual TM can be categorised as a certain type, namely Standard Type TM. Although similar in nature, the different TM types vary in their feature complexity. The common features to the Standard type TMs will be described in this section and the detailed operation will be described in the Standard Type TM section.

TM Function	STM
Timer/Counter	√
Input Capture	√
Compare Match Output	√
PWM Channels	1
Single Pulse Output	1
PWM Alignment	Edge
PWM Adjustment Period & Duty	Duty or Period

TM Function Summary

TM Operation

The different types of TM offer a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running count-up counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which

can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in each TM can originate from various sources. The selection of the required clock source is implemented using the STnCK2~STnCK0 bits in the STMn control registers, where "n" stands for the specific TM serial number. The clock source can be a ratio of the system clock, f_{SYS}, or the internal high clock, f_H, the f_{SUB} clock source or the external STCKn pin. The STCKn pin clock source is used to allow an external signal to drive the TM as an external clock source for event counting.

TM Interrupts

The Standard type TM has two internal interrupt, one for each of the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

TM External Pins

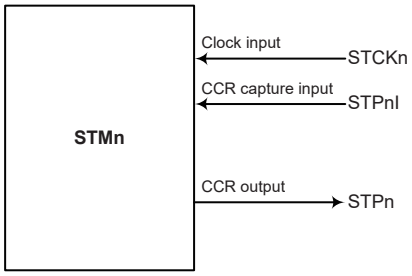
Each of the TMs has two TM input pins, with the label STCKn and STPnI. The STMn input pin, STCKn, is essentially a clock source for the STMn and is selected using the STnCK2~STnCK0 bits in the STMnC0 register. This external TM input pin allows an external clock source to drive the internal TM. The STCKn input pin can be chosen to have either a rising or falling active edge. The STCKn pin is also used as the external trigger input pin in single pulse output mode for the STM.

Another input pin, STPnI, is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the STnIO1~STnIO0 bits in the STMnC1 register.

The TMs each has an TM output pin, STPn. The TM output pin can be selected using the corresponding pin-shared function selection bits described in the Pin-shared Function section. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external STPn output pin is also the pin where the TM generates the PWM output waveform. As the TM output pins are pin-shared with other functions, the TM output function must first be setup using relevant pin-shared function selection register.

TM Input/Output Pin Selection

Selecting to have a TM input/output or whether to retain its other shared function is implemented using the relevant pin-shared function selection registers, with the corresponding selection bits in each pin-shared function register corresponding to a TM input/output pin. Configuring the selection bits correctly will setup the corresponding pin as a TM input/output. The details of the pin-shared function selection are described in the pin-shared function section.

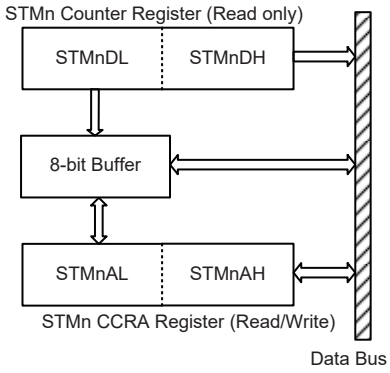


STM Function Pin Control Block Diagram (n=0~1)

Programming Considerations

The TM Counter Registers and the Capture/Compare CCRA register, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA register is implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the "MOV" instruction to access the CCRA low byte registers, named STMnAL, using the following access procedures. Accessing the CCRA low byte registers without following these access procedures will result in unpredictable values.



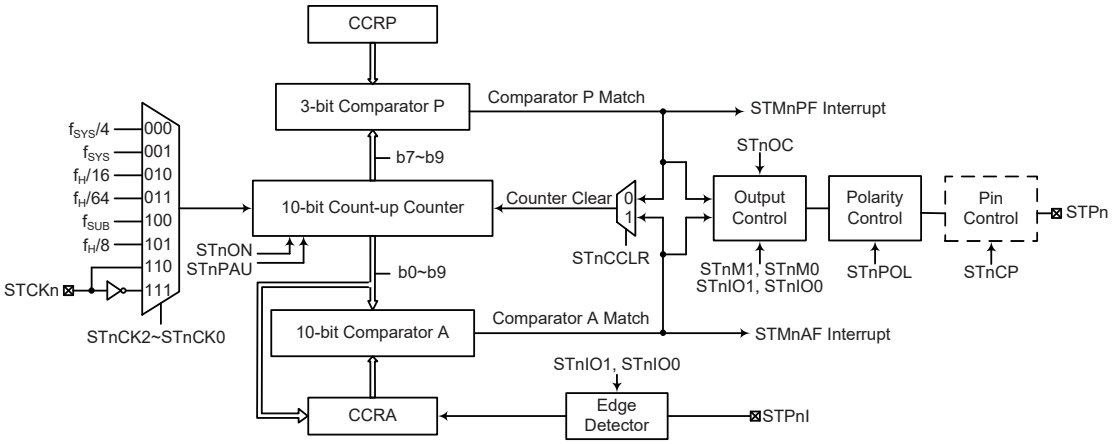
The following steps show the read and write procedures:

- Writing Data to CCRA
  - Step 1. Write data to Low Byte STMnAL
    - Note that here data is only written to the 8-bit buffer.
  - Step 2. Write data to High Byte STMnAH
    - Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the Low Byte registers.
- Reading Data from the Counter Registers and CCRA
  - Step 1. Read data from the High Byte STMnDH, STMnAH
    - Here data is read directly from the High Byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - Step 2. Read data from the Low Byte STMnDL, STMnAL
    - This step reads data from the 8-bit buffer.

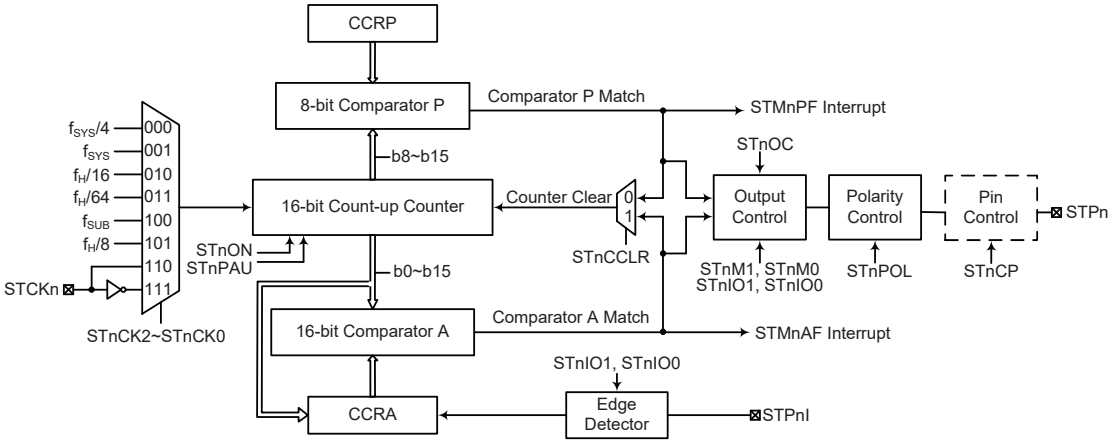
Standard Type TM – STM

The Standard Type TM contains five operating modes, which are Compare Match Output, Timer/ Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Standard TM can also be controlled with two external input pins and can drive one external output pin.

STM Core	STM Input Pins	STM Output Pin
10-bit STM (STM0)	STCK0, STP0I	STP0
16-bit STM (STM1)	STCK1, STP1I	STP1



10-bit Standard Type TM Block Diagram (n=0)



16-bit Standard Type TM Block Diagram (n=1)

Standard Type TM Operation

The size of Standard TM is 10-/16-bit wide and its core is a 10-/16-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP comparator is 3-/8-bit wide whose value is compared the with highest 3 or 8 bits in the counter while the CCRA is the 10/16 bits and therefore compares all counter bits.

The only way of changing the value of the 10-/16-bit counter using the application program, is to clear the counter by changing the STnON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators.

When these conditions occur, a STMn interrupt signal will also usually be generated. The Standard Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control an output pin. All operating setup conditions are selected using relevant internal registers.

Standard Type TM Register Description

Overall operation of the Standard TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-/16-bit value, while a read/write register pair exists to store the internal 10-/16-bit CCRA value. The STMnRP register for the 16-bit STM is used to store the 8-bit CCRP value. The remaining two registers are control registers which setup the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
STMnC0	STnPAU	STnCK2	STnCK1	STnCK0	STnON	STnRP2	STnRP1	STnRP0
STMnC1	STnM1	STnM0	STnIO1	STnIO0	STnOC	STnPOL	STnDPX	STnCCLR
STMnDL	D7	D6	D5	D4	D3	D2	D1	D0
STMnDH	—	—	—	—	—	—	D9	D8
STMnAL	D7	D6	D5	D4	D3	D2	D1	D0
STMnAH	—	—	—	—	—	—	D9	D8

10-bit Standard Type TM Registers List (n=0)

Register Name	Bit							
	7	6	5	4	3	2	1	0
STMnC0	STnPAU	STnCK2	STnCK1	STnCK0	STnON	—	—	—
STMnC1	STnM1	STnM0	STnIO1	STnIO0	STnOC	STnPOL	STnDPX	STnCCLR
STMnDL	D7	D6	D5	D4	D3	D2	D1	D0
STMnDH	D15	D14	D13	D12	D11	D10	D9	D8
STMnAL	D7	D6	D5	D4	D3	D2	D1	D0
STMnAH	D15	D14	D13	D12	D11	D10	D9	D8
STMnRP	D7	D6	D5	D4	D3	D2	D1	D0

16-bit Standard Type TM Registers List (n=1)

STMnDL Register (n=0~1)

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 STMn Counter Low Byte Register bit 7 ~ bit 0
STMn 10-/16-bit Counter bit 7 ~ bit 0

STMnDH Register (n=0)

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 STMn Counter High Byte Register bit 1 ~ bit 0
STMn 10-bit Counter bit 9 ~ bit 8

STMnDH Register (n=1)

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 STMn Counter High Byte Register bit 7 ~ bit 0
STMn 16-bit Counter bit 15 ~ bit 8

STMnAL Register (n=0~1)

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 STMn CCRA Low Byte Register bit 7 ~ bit 0
STMn 10-/16-bit CCRA bit 7 ~ bit 0

STMnAH Register (n=0)

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”
Bit 1~0 STMn CCRA High Byte Register bit 1 ~ bit 0
STMn 10-bit CCRA bit 9 ~ bit 8

STMnAH Register (n=1)

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 STMn CCRA High Byte Register bit 7 ~ bit 0
STMn 16-bit CCRA bit 15 ~ bit 8

STMnRP Register (n=1)

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: STMn CCRP 8-bit register, compared with the STMn counter bit 15~bit 8
Comparator P match period =
0: 65536 STMn clocks
1~255: (1~255) × 256 STMn clocks
These eight bits are used to setup the value on the internal CCRP 8-bit register, which are then compared with the internal counter's highest eight bits. The result of this comparison can be selected to clear the internal counter if the STnCCLR bit is set to zero. Setting the STnCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the highest eight counter bits, the compare values exist in 256 clock cycle multiples. Clearing all eight bits to zero is in effect allowing the counter to overflow at its maximum value.

STMnC0 Register (n=0)

Bit	7	6	5	4	3	2	1	0
Name	STnPAU	STnCK2	STnCK1	STnCK0	STnON	STnRP2	STnRP1	STnRP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **STnPAU**: STMn Counter Pause control
0: Run
1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the STMn will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **STnCK2~STnCK0**: Select STMn Counter clock
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: STCKn rising edge clock
111: STCKn falling edge clock

These three bits are used to select the clock source for the STMn. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **STnON**: STMn Counter On/Off control
0: Off
1: On

This bit controls the overall on/off function of the STMn. Setting the bit high enables the counter to run while clearing the bit disables the STMn. Clearing this bit to zero will stop the counter from counting and turn off the STMn which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again. If the STMn is in the Compare Match Output Mode then the STMn output pin will be reset to its initial condition, as specified by the STnOC bit, when the STnON bit changes from low to high.

Bit 2~0 **STnRP2~STnRP0**: STMn CCRP 3-bit register, compared with the STMn Counter bit 9~bit 7

Comparator P Match Period
000: 1024 STMn clocks
001: 128 STMn clocks
010: 256 STMn clocks
011: 384 STMn clocks
100: 512 STMn clocks
101: 640 STMn clocks
110: 768 STMn clocks
111: 896 STMn clocks

These three bits are used to setup the value on the internal CCRP 3-bit register, which are then compared with the internal counter's highest three bits. The result of this comparison can be selected to clear the internal counter if the STnCCLR bit is set to zero. Setting the STnCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the

highest three counter bits, the compare values exist in 128 clock cycle multiples. Clearing all three bits to zero is in effect allowing the counter to overflow at its maximum value.

STMnC0 Register (n=1)

Bit	7	6	5	4	3	2	1	0
Name	STnPAU	STnCK2	STnCK1	STnCK0	STnON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

Bit 7 **STnPAU**: STMn Counter Pause control
0: Run
1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the STMn will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **STnCK2~STnCK0**: Select STMn Counter clock
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: STCKn rising edge clock
111: STCKn falling edge clock

These three bits are used to select the clock source for the STMn. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **STnON**: STMn Counter On/Off control
0: Off
1: On

This bit controls the overall on/off function of the STMn. Setting the bit high enables the counter to run while clearing the bit disables the STMn. Clearing this bit to zero will stop the counter from counting and turn off the STMn which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again. If the STMn is in the Compare Match Output Mode then the STMn output pin will be reset to its initial condition, as specified by the STnOC bit, when the STnON bit changes from low to high.

Bit 2~0 Unimplemented, read as “0”

STMnC1 Register (n=0~1)

Bit	7	6	5	4	3	2	1	0
Name	STnM1	STnM0	STnIO1	STnIO0	STnOC	STnPOL	STnDPX	STnCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **STnM1~STnM0**: Select STMn Operating Mode
00: Compare Match Output Mode
01: Capture Input Mode
10: PWM Output Mode or Single Pulse Output Mode
11: Timer/Counter Mode

These bits setup the required operating mode for the STMn. To ensure reliable operation the STMn should be switched off before any changes are made to the STnM1 and STnM0 bits. In the Timer/Counter Mode, the STMn output pin control will be disabled.

Bit 5~4 **STnIO1~STnIO0**: Select STMn external pin STPn function

Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output

PWM Output Mode/Single Pulse Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Single Pulse Output

Capture Input Mode
00: Input capture at rising edge of STPnI
01: Input capture at falling edge of STPnI
10: Input capture at rising/falling edge of STPnI
11: Input capture disabled

Timer/Counter Mode
Unused

These two bits are used to determine how the STMn output pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the STMn is running.

In the Compare Match Output Mode, the STnIO1 and STnIO0 bits determine how the STMn output pin changes state when a compare match occurs from the Comparator A. The TM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the STMn output pin should be setup using the STnOC bit in the STMnC1 register. Note that the output level requested by the STnIO1 and STnIO0 bits must be different from the initial value setup using the STnOC bit otherwise no change will occur on the STMn output pin when a compare match occurs. After the STMn output pin changes state, it can be reset to its initial level by changing the level of the STnON bit from low to high.

In the PWM Output Mode, the STnIO1 and STnIO0 bits determine how the STMn output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the STnIO1 and STnIO0 bits only after the STMn has been switched off. Unpredictable PWM outputs will occur if the STnIO1 and STnIO0 bits are changed when the STMn is running.

Bit 3 **STnOC**: STMn STPn Output control

Compare Match Output Mode
0: Initial low
1: Initial high

PWM Output Mode/Single Pulse Output Mode
0: Active low
1: Active high

This is the output control bit for the STMn output pin. Its operation depends upon whether STM is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the STM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the STM output pin before a compare match occurs. In the PWM output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the STMn output pin when the STnON bit changes from low to high.

Bit 2 **STnPOL**: STMn STPn Output polarity control
0: Non-inverted
1: Inverted

This bit controls the polarity of the STPn output pin. When the bit is set high the STMn output pin will be inverted and not inverted when the bit is zero. It has no effect if the STMn is in the Timer/Counter Mode.

Bit 1 **STnDPX**: STMn PWM duty/period control
0: CCRP – period; CCRA – duty
1: CCRP – duty; CCRA – period

This bit determines which of the CCRA and CCRP registers are used for period and duty control of the PWM waveform.

Bit 0 **STnCCLR**: STMn Counter Clear condition selection
0: Comparator P match
1: Comparator A match

This bit is used to select the method which clears the counter. Remember that the Standard Type TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the STnCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The STnCCLR bit is not used in the PWM Output, Single Pulse Output or Capture Input Mode.

Standard Type TM Operation Modes

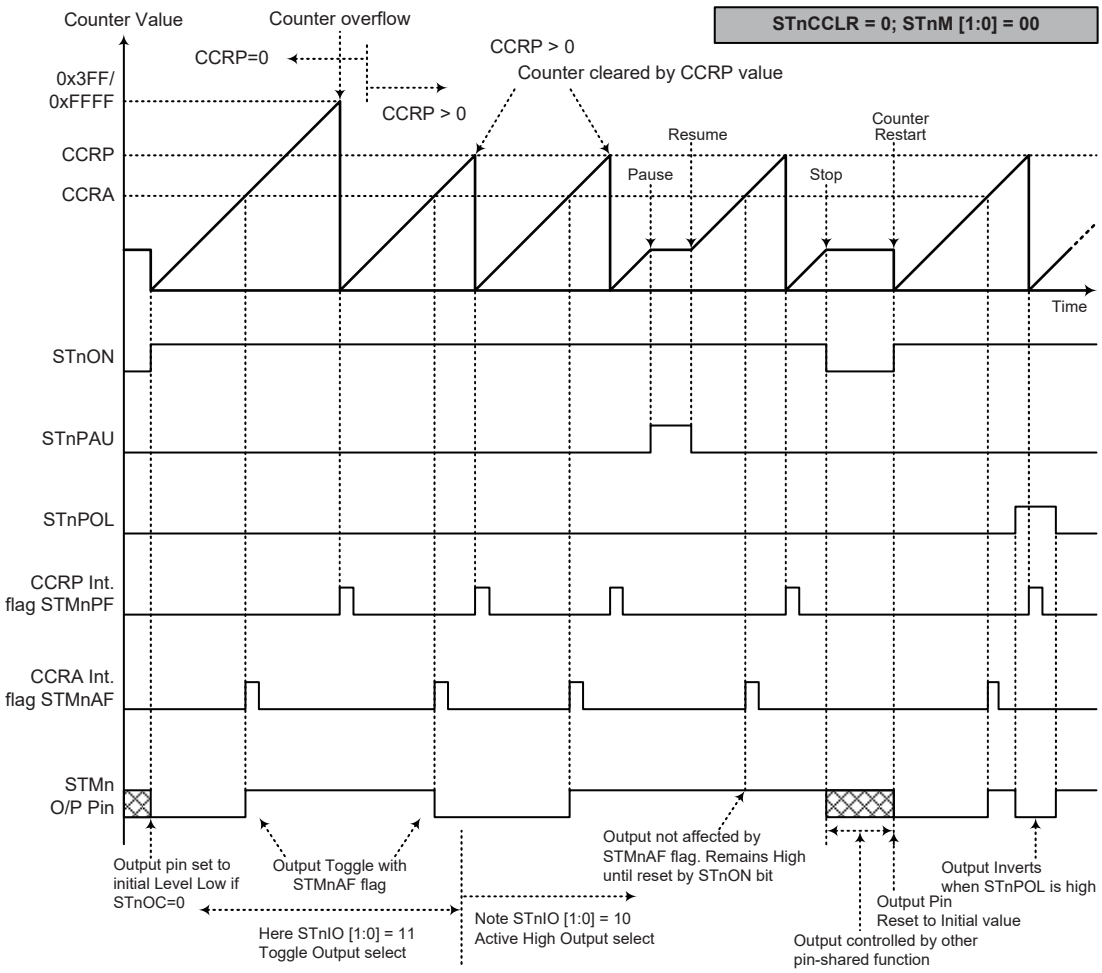
The Standard Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the STnM1 and STnM0 bits in the STMnC1 register.

Compare Match Output Mode

To select this mode, bits STnM1 and STnM0 in the STMnC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the STnCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both STMnAF and STMnPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

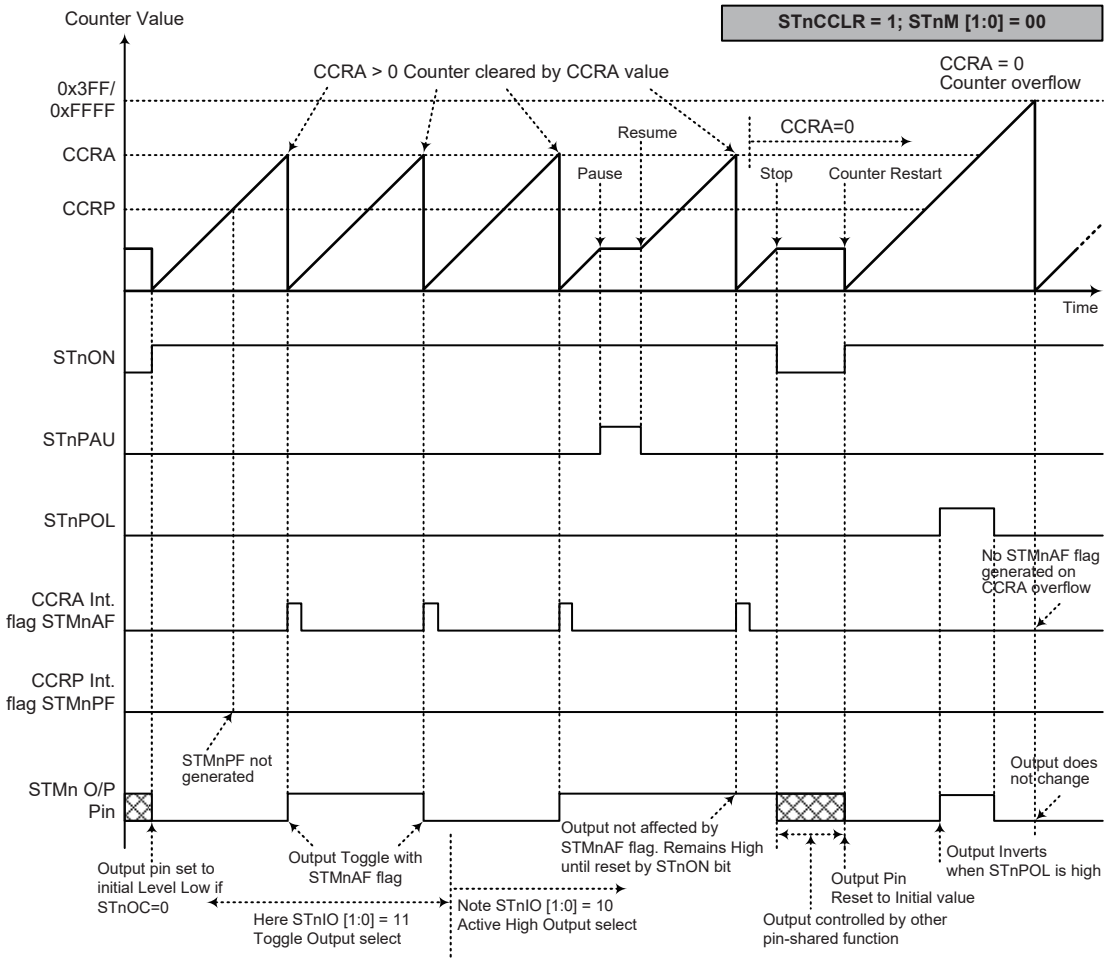
If the STnCCLR bit in the STMnC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the STMnAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when STnCCLR is high no STMnPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA can not be set to “0”.

As the name of the mode suggests, after a comparison is made, the STMn output pin, will change state. The STMn output pin condition however only changes state when a STMnAF interrupt request flag is generated after a compare match occurs from Comparator A. The STMnPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the STMn output pin. The way in which the STMn output pin changes state are determined by the condition of the STnIO1 and STnIO0 bits in the STMnC1 register. The STMn output pin can be selected using the STnIO1 and STnIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the STMn output pin, which is setup after the STnON bit changes from low to high, is setup using the STnOC bit. Note that if the STnIO1 and STnIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – STnCCLR = 0

Note: 1. With STnCCLR=0 a Comparator P match will clear the counter
2. The STMn output pin is controlled only by the STMnAF flag
3. The output pin is reset to its initial state by a STnON bit rising edge
4. n=0 for 10-bit STM while n=1 for 16-bit STM



Compare Match Output Mode – STnCCLR = 1

Note: 1. With STnCCLR=1 a Comparator A match will clear the counter
2. The STMn output pin is controlled only by the STMnAF flag
3. The output pin is reset to its initial state by a STnON bit rising edge
4. A STMnPF flag is not generated when STnCCLR=1
5. n=0 for 10-bit STM while n=1 for 16-bit STM

Timer/Counter Mode

To select this mode, bits STnM1 and STnM0 in the STMnC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the STMn output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the STMn output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits STnM1 and STnM0 in the STMnC1 register should be set to 10 respectively and also the STnIO1 and STnIO0 bits should be set to 10 respectively. The PWM function within the STMn is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the STMn output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the STnCCLR bit has no effect as the PWM period. Both of the CCRA and CCRP registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. Which register is used to control either frequency or duty cycle is determined using the STnDPX bit in the STMnC1 register. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The STnOC bit in the STMnC1 register is used to select the required polarity of the PWM waveform while the two STnIO1 and STnIO0 bits are used to enable the PWM output or to force the STMn output pin to a fixed high or low level. The STnPOL bit is used to reverse the polarity of the PWM output waveform.

- **10-bit STM, PWM Output Mode, Edge-aligned Mode, STnDPX=0**

CCRP	1~7	0
Period	CCRP × 128	1024
Duty	CCRA	

If f_{SYS}=4MHz, STM clock source is f_{SYS}/4, CCRP=2 and CCRA=128,

The STM PWM output frequency=(f_{SYS}/4)/(2×128)=f_{SYS}/1024=4kHz, duty=128/(2×128)=50%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

- **10-bit STM, PWM Output Mode, Edge-aligned Mode, STnDPX=1**

CCRP	1~7	0
Period	CCRA	
Duty	CCRP×128	1024

The PWM output period is determined by the CCRA register value together with the STMn clock while the PWM duty cycle is defined by the CCRP register value except when the CCRP value is equal to 0.

- **16-bit STM, PWM Output Mode, Edge-aligned Mode, STnDPX=0**

CCRP	1~255	0
Period	CCRP × 256	65536
Duty	CCRA	

If f_{SYS}=4MHz, STM clock source is f_{SYS}/4, CCRP=2 and CCRA=128,

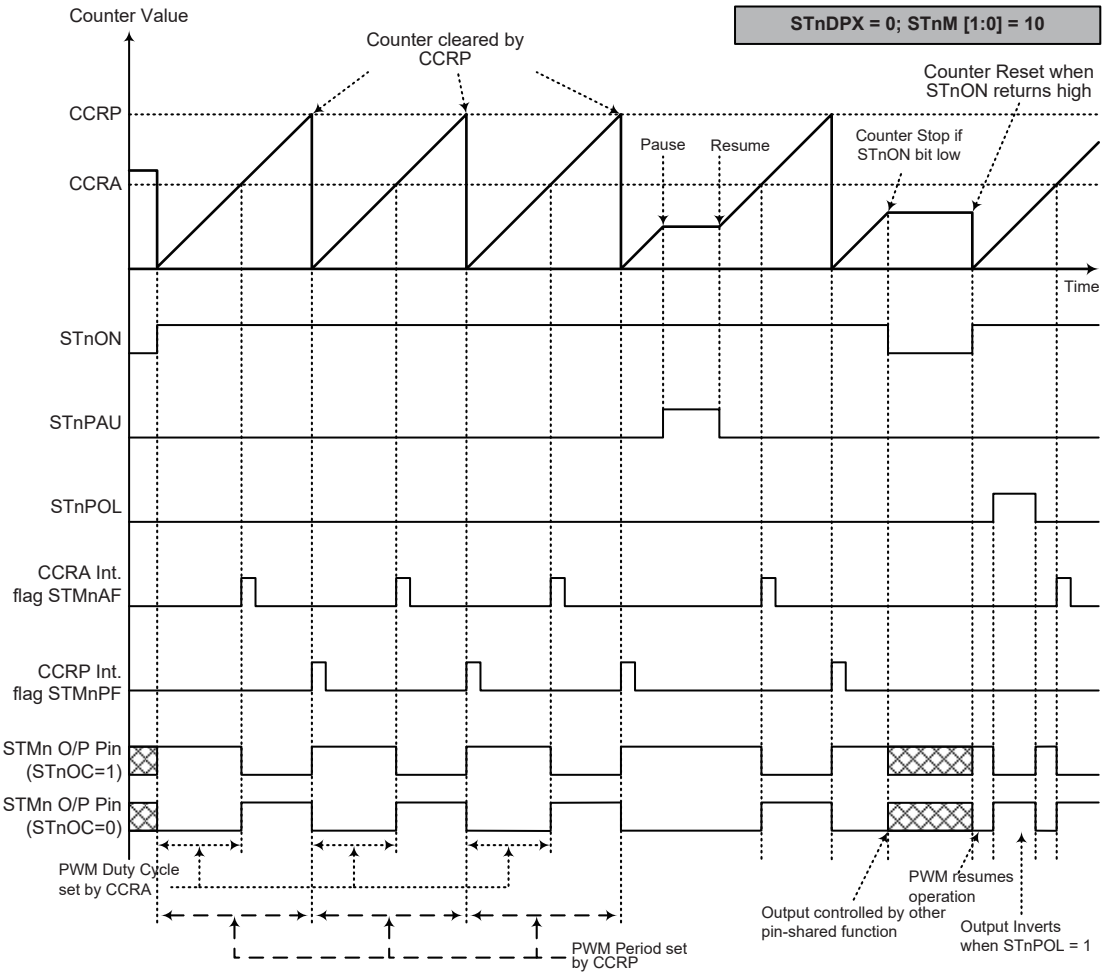
The STM PWM output frequency=(f_{SYS}/4)/(2×256)=f_{SYS}/2048=2kHz, duty=128/(2×256)=25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

- **16-bit STM, PWM Output Mode, Edge-aligned Mode, STnDPX=1**

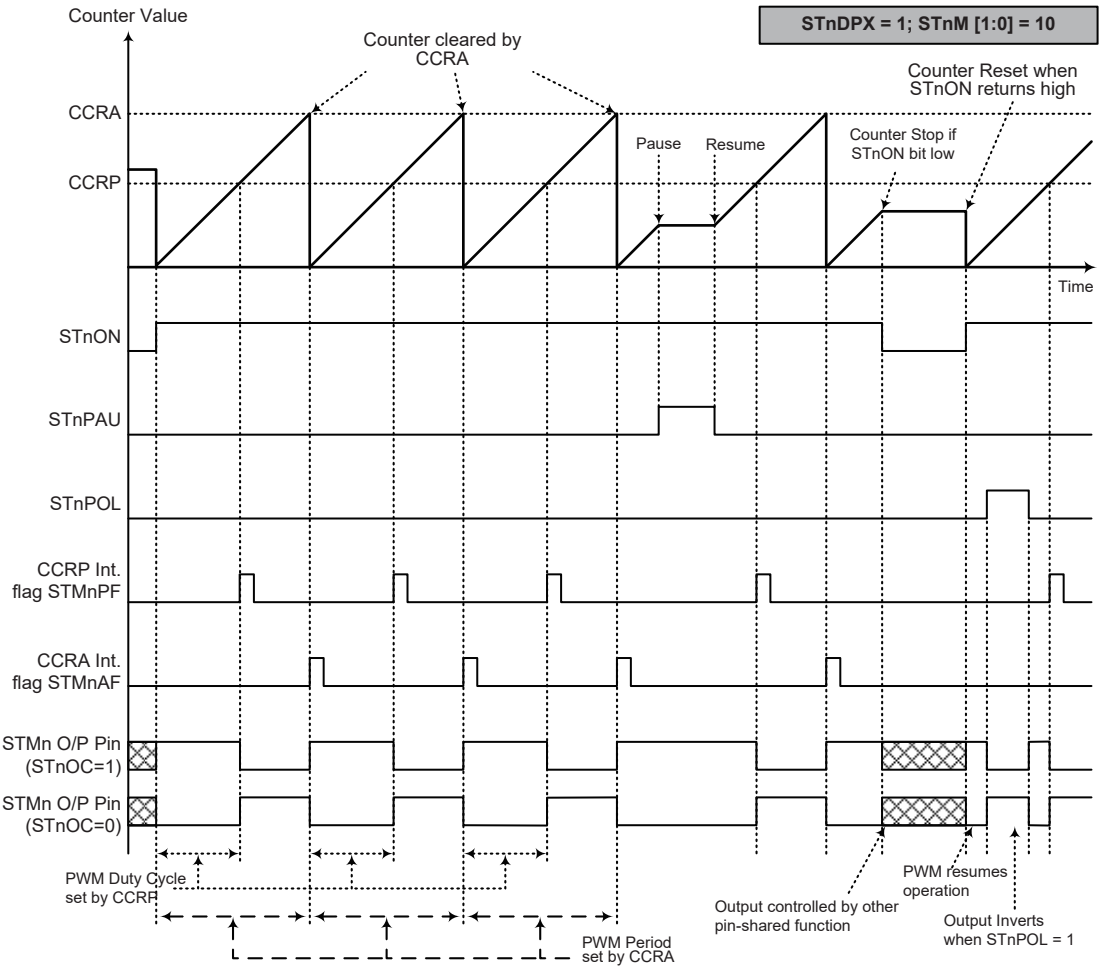
CCRP	1~255	0
Period	CCRA	
Duty	CCRP×256	65536

The PWM output period is determined by the CCRA register value together with the STMn clock while the PWM duty cycle is defined by the CCRP register value except when the CCRP value is equal to 0.



PWM Output Mode – STnDPX = 0

Note: 1. Here STnDPX=0 – Counter cleared by CCRP
2. A counter clear sets the PWM Period
3. The internal PWM function continues running even when STnIO [1:0]=00 or 01
4. The STnCCLR bit has no influence on PWM operation
5. n=0 for 10-bit STM while n=1 for 16-bit STM



PWM Output Mode – STnDPX = 1

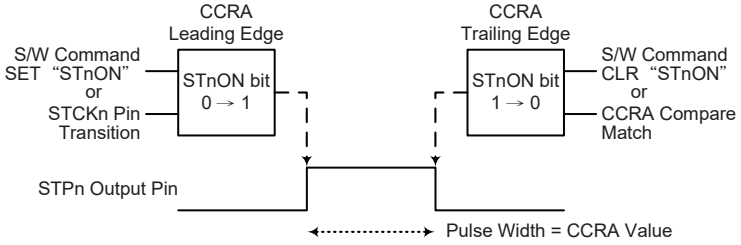
Note: 1. Here STnDPX=1 – Counter cleared by CCRA
2. A counter clear sets the PWM Period
3. The internal PWM function continues even when STnIO [1:0]=00 or 01
4. The STnCCLR bit has no influence on PWM operation
5. n=0 for 10-bit STM while n=1 for 16-bit STM

Single Pulse Output Mode

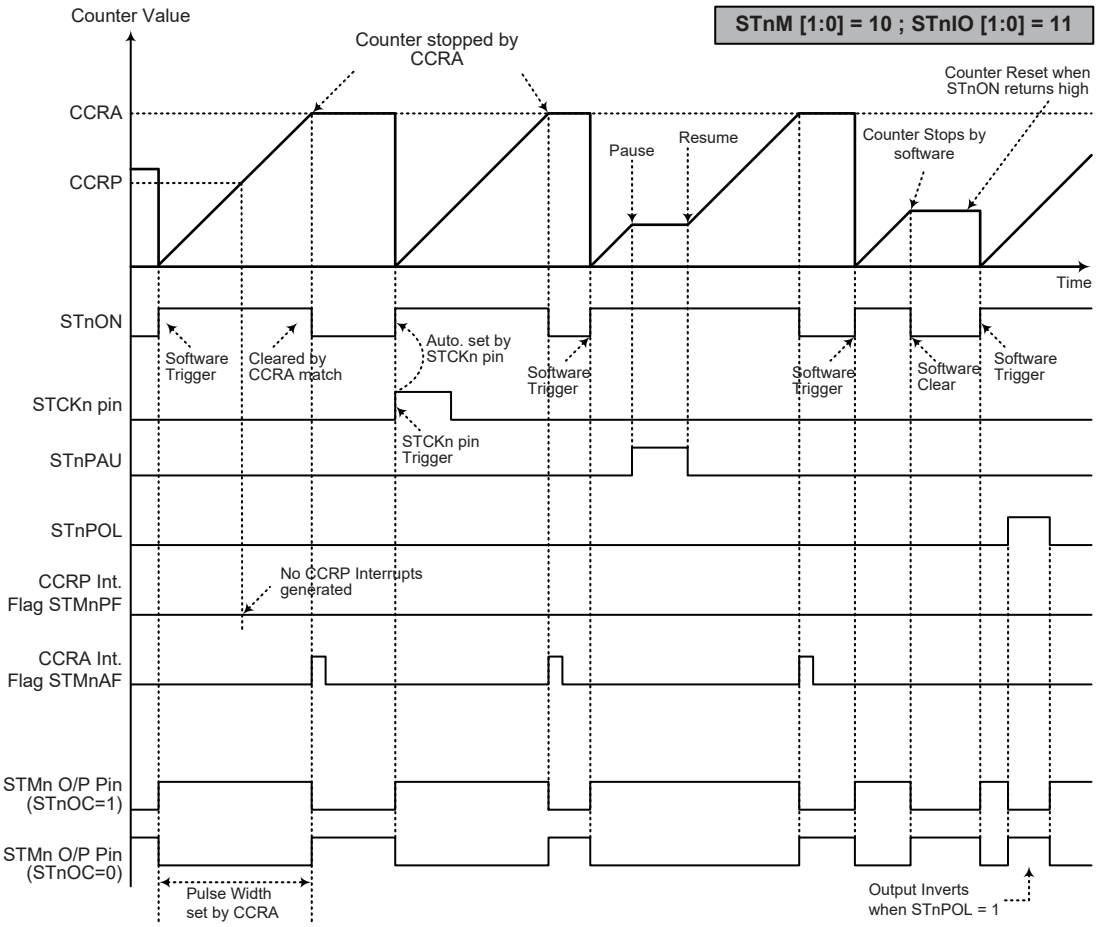
To select this mode, bits STnM1 and STnM0 in the STMnC1 register should be set to 10 respectively and also the STnIO1 and STnIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the STMn output pin.

The trigger for the pulse output leading edge is a low to high transition of the STnON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the STnON bit can also be made to automatically change from low to high using the external STCKn pin, which will in turn initiate the Single Pulse output. When the STnON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The STnON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the STnON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the STnON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a STMn interrupt. The counter can only be reset back to zero when the STnON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The STnCCLR and STnDPX bits are not used in this Mode.



Single Pulse Generation



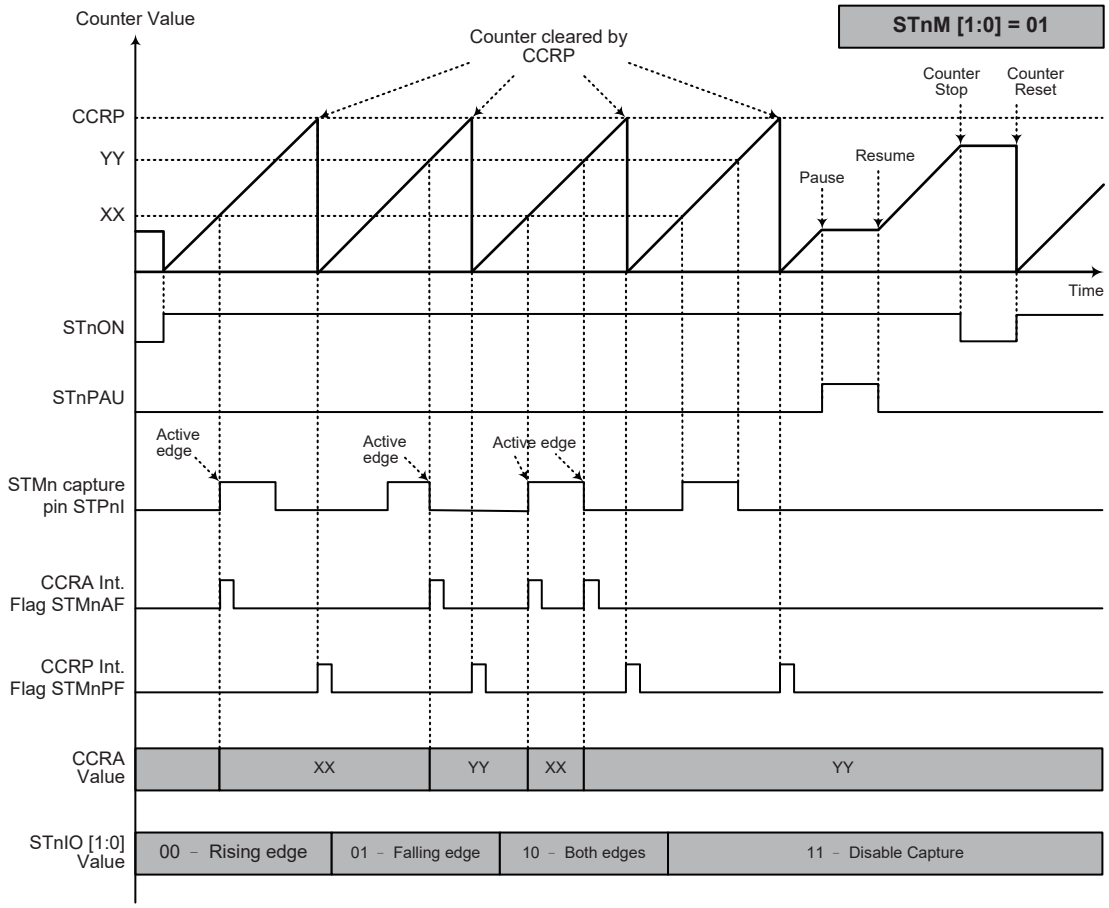
Single Pulse Output Mode

Note: 1. Counter stopped by CCRA
2. CCRP is not used
3. The pulse triggered by the STnCK pin or by setting the STnON bit high
4. A STCKn pin active edge will automatically set the STnON bit high.
5. In the Single Pulse Output Mode, STnIO [1:0] must be set to “11” and can not be changed.
6. n=0 for 10-bit STM while n=1 for 16-bit STM

Capture Input Mode

To select this mode bits STnM1 and STnM0 in the STMnC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the STPnI pin, whose active edge can be a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the STnIO1 and STnIO0 bits in the STMnC1 register. The counter is started when the STnON bit changes from low to high which is initiated using the application program.

When the required edge transition appears on the STPnI pin the present value in the counter will be latched into the CCRA registers and a STMn interrupt generated. Irrespective of what events occur on the STPnI pin the counter will continue to free run until the STnON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a STMn interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The STnIO1 and STnIO0 bits can select the active trigger edge on the STPnI pin to be a rising edge, falling edge or both edge types. If the STnIO1 and STnIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the STPnI pin, however it must be noted that the counter will continue to run. The STnCCLR and STnDPX bits are not used in this Mode.



Capture Input Mode

Note: 1. STnM [1:0]=01 and active edge set by the STnIO [1:0] bits
2. A STMn Capture input pin active edge transfers the counter value to CCRA
3. STnCCLR bit not used
4. No output function – STnOC and STnPOL bits are not used
5. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero.
6. n=0 for 10-bit STM while n=1 for 16-bit STM

Analog to Digital Converter

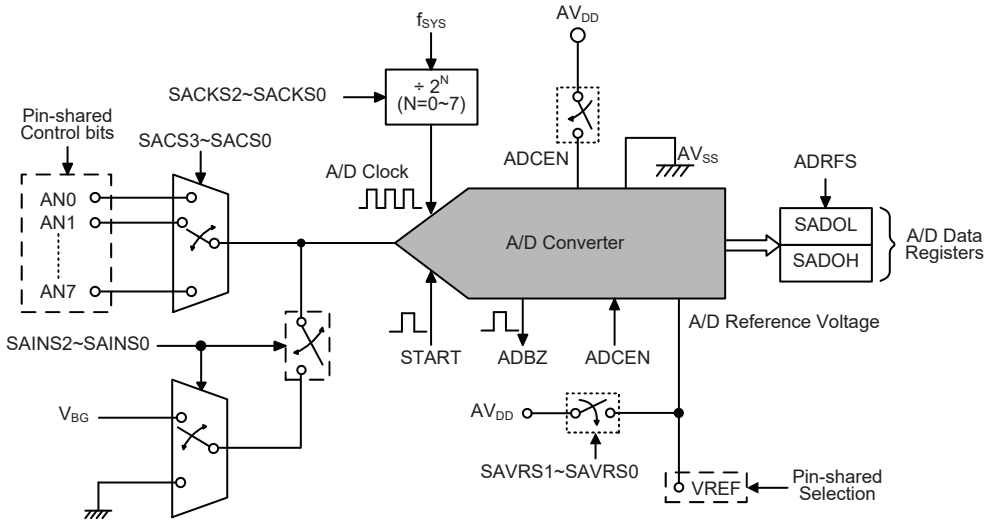
The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

A/D Overview

The device contains a multi-channel analog to digital converter which can directly interface to external analog signals, such as that from sensors or other control signals and convert these signals directly into a 12-bit digital value. It also can convert the internal signals, such as the internal reference voltage, into a 12-bit digital value. The external or internal analog signal to be converted is determined by the SAINS and SACS bit fields. More detailed information about the A/D input signal selection will be described in the "A/D Converter Input Signals" section.

The accompanying block diagram shows the overall internal structure of the A/D converter, together with its associated registers and control bits.

External Input Channels	Internal Input Signal	A/D Signal Select
AN0~AN7	V_{BG}	SAINS2~SAINS0 SACS3~SACS0



A/D Converter Structure

Registers Descriptions

Overall operation of the A/D converter is controlled using four registers. A read only register pair exists to store the A/D Converter data 12-bit value. Two registers, SADC0 and SADC1, are the control registers which setup the operating conditions and control function of the A/D converter.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRFS=0)	D3	D2	D1	D0	—	—	—	—
SADOL (ADRFS=1)	D7	D6	D5	D4	D3	D2	D1	D0
SADOH (ADRFS=0)	D11	D10	D9	D8	D7	D6	D5	D4
SADOH (ADRFS=1)	—	—	—	—	D11	D10	D9	D8
SADC0	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
SADC1	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0

A/D Converter Registers List

A/D Converter Data Registers – SADOL, SADOH

As the device contains an internal 12-bit A/D converter, it requires two data registers to store the converted value. These are a high byte register, known as SADOH, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 12 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRFS bit in the SADC0 register as shown in the accompanying table. D0~D11 are the A/D conversion result data bits. Any unused bits will be read as zero. The A/D data registers contents will be unchanged if the A/D converter is disabled.

ADRFS	SADOH								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0
1	0	0	0	0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

A/D Converter Data Registers

A/D Converter Control Registers – SADC0, SADC1

To control the function and operation of the A/D converter, two control registers known as SADC0 and SADC1 are provided. These 8-bit registers define functions such as the selection of which analog signal is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS field in the SADC1 register and SACS field in the SADC0 register are used to determine which analog signal derived from the external or internal signals will be connected to the A/D converter.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

- **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **START**: Start the A/D Conversion
0→1→0: Start
This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.

Bit 6 **ADBZ**: A/D Converter busy flag
0: No A/D conversion is in progress
1: A/D conversion is in progress
This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.

Bit 5 **ADCEN**: A/D Converter function enable control
0: Disable
1: Enable
This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is set low, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be unchanged.

Bit 4 **ADRFS**: A/D conversion data format select
0: A/D converter data format → SADOH = D [11:4]; SADOL = D [3:0]
1: A/D converter data format → SADOH = D [11:8]; SADOL = D [7:0]
This bit controls the format of the 12-bit converted A/D value in the two A/D data registers. Details are provided in the A/D converter data register section.

Bit 3~0 **SACS3~SACS0**: A/D converter external analog input channel select
0000: External AN0 input
0001: External AN1 input
0010: External AN2 input
0011: External AN3 input
0100: External AN4 input
0101: External AN5 input
0110: External AN6 input
0111: External AN7 input
1xxx: Non-existed channel, the input will be floating if selected.
These bits are used to select which external analog input channel is to be converted. When the external analog input channel is selected, the SAINS bit field must set to “000”, “101” or “11x”. Details are summarized in the “A/D Converter Input Signal Selection” table.

- **SADC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~5 **SAINS2~SAINS0**: A/D converter input signal select
000: External source – External analog channel intput, ANn
001: Internal source – Internal signal derived from V_{BG}
010: Internal source – Unused, connected to ground
011: Internal source – Unused, connected to ground
100: Internal source – Unused, connected to ground
101: External source – External analog channel intput, ANn
11x: External source – External analog channel intput, ANn

Care must be taken if the SAINS2~SAINS0 bits are set to "001", "01x" and "100" to select the internal analog signal to be coverted. When the internal analog signal is selected to be converted, the external input pin must never be selected as the A/D input signal by properly setting the SACS3~SACS0 bits with a value from "1000" to "1111". Otherwise, the external channel input will be connected together with the internal analog signal. This will result in unpredictable situations such as an irreversible damage.

Bit 4~3 **SAVRS2~SAVRS0**: A/D converter reference voltage select
00: External VREF pin
01: Internal A/D converter power, AV_{DD}
1x: External VREF pin

These bits are used to select the A/D converter reference voltage. Care must be taken if the SAVRS1~SAVRS0 bits are set to "01" to select the internal A/D converter power as the reference voltage source. When the internal A/D converter power is selected as the reference voltage, the VREF pin cannot be configured as the reference voltage input by properly configuring the corresponding pin-shared function control bits. Otherwise, the external input voltage on VREF pin will be connected to the internal A/D converter power. This will result in unpredictable situations.

Bit 2~0 **SACKS2~SACKS0**: A/D conversion clock source select
000: f_{SYS}
001: $f_{SYS}/2$
010: $f_{SYS}/4$
011: $f_{SYS}/8$
100: $f_{SYS}/16$
101: $f_{SYS}/32$
110: $f_{SYS}/64$
111: $f_{SYS}/128$

These bits are used to select the clock source for the A/D converter.

A/D Converter Reference Voltage

The actual reference voltage supply to the A/D Converter can be supplied from the positive power supply pin, AVDD, or an external reference source supplied on pin VREF determined by the SAVRS1~SAVRS0 bits in the SADC1 register. As the VREF pin is pin-shared with other functions, when the VREF pin is selected as the reference voltage pin, the VREF pin-shared function selection bits should first be properly configured to disable other pin-shared functions. However, if the internal reference signal is selected as the reference source, the VREF pin must not be configured as the reference voltage input to avoid the internal connection between the VREF pin to A/D converter power AV_{DD}. The analog input values must not be allowed to exceed the value of the selected A/D reference voltage.

A/D Converter Input Signals

All of the external A/D analog input pins are pin-shared with the I/O pins as well as other functions. The corresponding pin-shared function selection bits in the PxS1 and PxS0 registers, determine whether the external input pins are setup as A/D converter analog channel inputs or whether they have other functions. If the corresponding pin is setup to be an A/D converter analog channel input, the original pin function will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull-high resistors, which are setup through register programming, will be automatically disconnected if the pins are setup as A/D inputs. Note that it is not necessary to first setup the A/D pin as an input in the port control register to enable the A/D input as when the relevant A/D input function selection bits enable an A/D input, the status of the port control register will be overridden.

As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS2~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the external channel input or internal analog signal. The SACS3~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. If the SAINS2~SAINS0 bits are set to "000" or "101~111", the external channel input will be selected to be converted and the SACS3~SACS0 bits can determine which external channel is selected. If the internal analog signal is selected to be converted, the SACS3~SACS0 bits must be configured with an appropriate value to switch off the external analog channel input. Otherwise, the internal analog signal will be connected together with the external channel input. This will result in unpredictable situations.

SAINS[2:0]	SACS[3:0]	Input Signals	Description
000, 101~111	0000~0111	AN0~AN7	External pin analog input
	1000~1111	—	Un-existed channel, input is floating.
001	1000~1111	V_{BG}	Internal Bandgap reference voltage
010~100	1000~1111	GND	Unused, connected to ground

A/D Converter Input Signal Selection

A/D Operation

The START bit in the SADC0 register is used to start the A/D conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ bit will be cleared to 0. In addition, the corresponding A/D interrupt request flag will be set in the interrupt control register, and if the interrupts are enabled, an internal interrupt signal will be generated. This A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock f_{SYS}, can be chosen to be either f_{SYS} or a subdivided version of f_{SYS}. The division ratio value is determined by the SACKS2~SACKS0 bits in the SADC1 register. Although the A/D clock source is determined by the system clock f_{SYS} and by bits SACKS2~SACKS0, there are some limitations on the maximum A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period, t_{ADCK}, is from 0.5μs to 10μs, care must be taken for system clock frequencies. For example, if

the system clock operates at a frequency of 4MHz, the SACKS2~SACKS0 bits should not be set to 000, 110 or 111. Doing so will give A/D clock periods that are less than the minimum or larger than the maximum A/D clock period which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk * show where, depending upon the device, special care must be taken, as the values may be less than or larger than the specified A/D Clock Period.

f_{SYS}	A/D Clock Period (t_{ADCK})							
	SACKS [2:0]=000 (f_{SYS})	SACKS [2:0]=001 ($f_{SYS}/2$)	SACKS [2:0]=010 ($f_{SYS}/4$)	SACKS [2:0]=011 ($f_{SYS}/8$)	SACKS [2:0]=100 ($f_{SYS}/16$)	SACKS [2:0]=101 ($f_{SYS}/32$)	SACKS [2:0]=110 ($f_{SYS}/64$)	SACKS [2:0]=111 ($f_{SYS}/128$)
1MHz	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *	128μs *
2MHz	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *
4MHz	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *

A/D Clock Period Examples

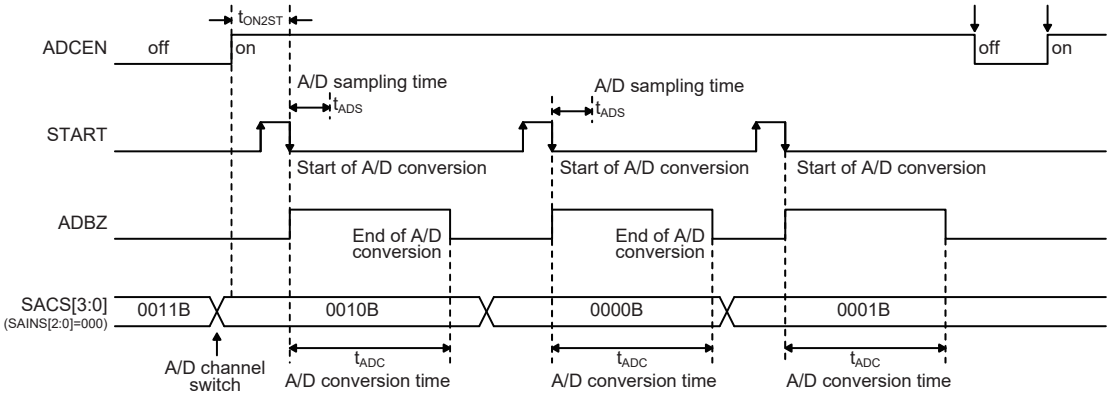
Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry a certain delay, as indicated in the timing diagram, must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

Conversion Rate and Timing Diagram

A complete A/D conversion contains two parts, data sampling and data conversion. The data sampling which is defined as t_{ADS} takes 4 A/D clock cycles and the data conversion takes 12 A/D clock cycles. Therefore a total of 16 A/D clock cycles for an analog signal A/D conversion which is defined as t_{ADC} are necessary.

Maximum single A/D conversion rate = A/D clock period / 16

The accompanying diagram shows graphically the various stages involved in an analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for the A/D conversion is 16 t_{ADCK} clock cycles where t_{ADCK} is equal to the A/D clock period.



A/D Conversion Timing

Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1
  Select the required A/D conversion clock by correctly programming bits SACKS2~SACKS0 in the SADC1 register.
- Step 2
  Enable the A/D converter by setting the ADCEN bit in the SADC0 register to 1.
- Step 3
  Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS2~SAINS0 bits
  Select the external channel input to be converted, go to Step 4.
  Select the internal analog signal to be converted, go to Step 5.
- Step 4
  If the A/D input signal comes from the external channel input selected by configuring the SAINS bit field, the corresponding pins should be configured as A/D input function by configuring the relevant pin-shared function control bits. The desired analog channel then should be selected by configuring the SACS bit field. After this step, go to Step 6.
- Step 5
  Before the A/D input signal is selected to come from the internal analog signal by configuring the SAINS bit field, the corresponding external input pin must be switched to a non-existed channel input by properly configured the SACS3~SACS0 bits. The desired internal analog signal then can be selected by configuring the SAINS bit field. After this step, go to Step 6.
- Step 6
  Select the reference voltage source by configuring the SAVRS1~SAVRS0 bits in the SADC1 register.
- Step 7
  Select A/D converter output data format by setting the ADRFS bit in the SADC0 register.
- Step 8
  If A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.
- Step 9
  The A/D conversion procedure can now be initialized by setting the START bit from low to high and then low again.
- Step 10
  If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by setting bit ADCEN low in the SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/Os, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

A/D Transfer Function

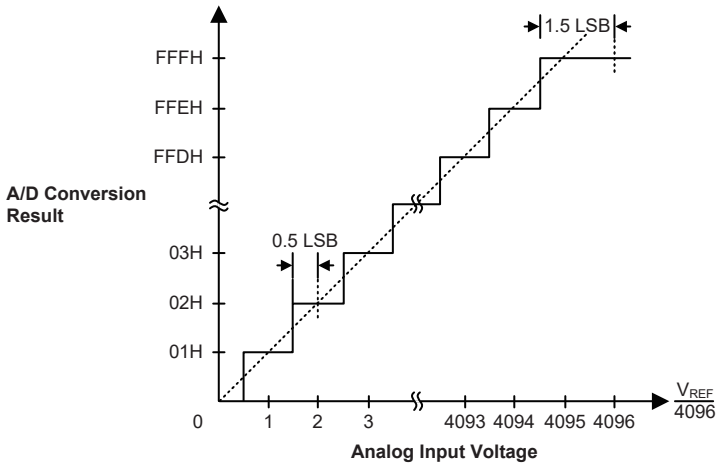
As the device contains a 12-bit A/D converter, its full-scale converted digitised value is equal to FFFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage, V_{REF}, this gives a single bit analog input value of reference voltage value divided by 4096.

$$1\ LSB = V_{REF} \div 4096$$

The A/D Converter input voltage value can be calculated using the following equation:

$$A/D\ input\ voltage = A/D\ output\ digital\ value \times V_{REF} \div 4096$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the V_{REF} level.Note that here the V_{REF} voltage is the actual A/D converter reference voltage determined by the SAVRS field.



Ideal A/D Transfer Function

A/D Programming Examples

The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example: using an ADBZ polling method to detect the end of conversion

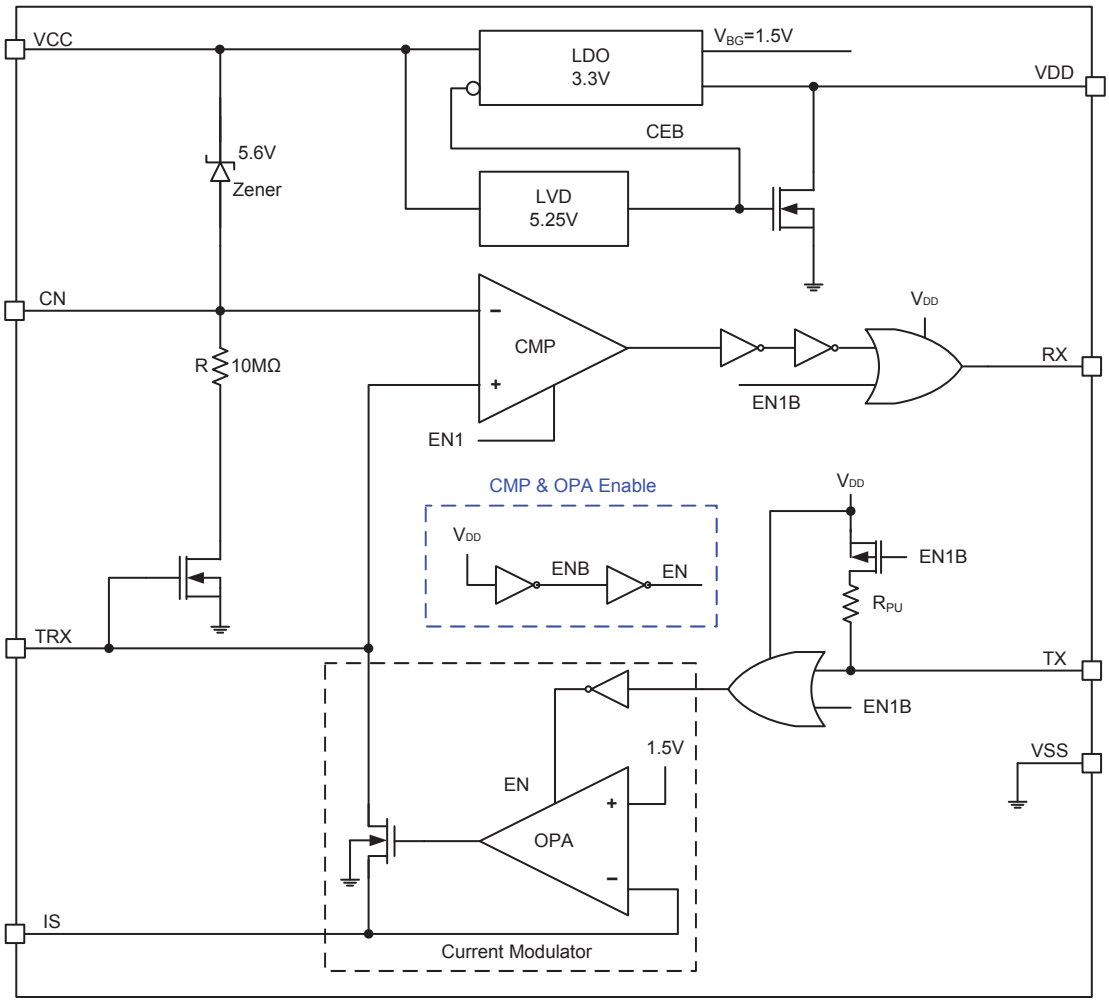
```
clr  ADE              ; disable ADC interrupt
mov  a,03H
mov  SADC1,a          ; select fSYS/8 as A/D clock
set  ADCEN
mov  a,02h            ; setup PBS0 register to configure pin AN0
mov  PBS0,a
mov  a,20h
mov  SADC0,a          ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr  START            ; high pulse on start bit to initiate conversion
set  START            ; reset A/D
clr  START            ; start A/D
polling_EOC:
sz   ADBZ             ; poll the SADC0 register ADBZ bit to detect end of A/D conversion
jmp  polling_EOC      ; continue polling
mov  a,SADOL          ; read low byte conversion result value
mov  SADOL_buffer,a   ; save result to user defined register
mov  a,SADOH          ; read high byte conversion result value
mov  SADOH_buffer,a   ; save result to user defined register
:
:
jmp  start_conversion
```

Example: using the interrupt method to detect the end of conversion

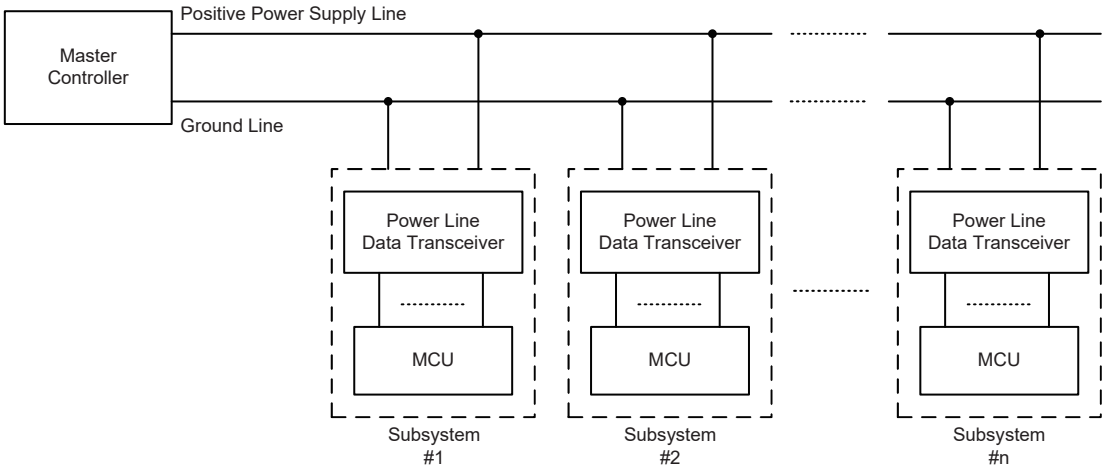
```
clr  ADE              ; disable ADC interrupt
mov  a,03H
mov  SADC1,a          ; select fSYS/8 as A/D clock
set  ADCEN
mov  a, 02h           ; setup PBS0 register to configure pin AN0
mov  PBS0,a
mov  a,20h
mov  SADC0,a          ; enable and connect AN0 channel to A/D converter
Start_conversion:
clr  START            ; high pulse on START bit to initiate conversion
set  START            ; reset A/D
clr  START            ; start A/D
clr  ADF              ; clear ADC interrupt request flag
set  ADE              ; enable ADC interrupt
set  EMI              ; enable global interrupt
:
:
                      ; ADC interrupt service routine
ADC_ISR:
mov  acc_stack,a      ; save ACC to user defined memory
mov  a,STATUS
mov  status_stack,a   ; save STATUS to user defined memory
:
:
mov  a,SADOL          ; read low byte conversion result value
mov  SADOL_buffer,a   ; save result to user defined register
mov  a,SADOH          ; read high byte conversion result value
mov  SADOH_buffer,a   ; save result to user defined register
:
:
EXIT_INT_ISR:
mov  a,status_stack
mov  STATUS,a         ; restore STATUS from user defined memory
mov  a,acc_stack      ; restore ACC from user defined memory
reti
```

Power Line Data Transceiver

The power line data transceiver provides a way to transmit and receive data on the common power lines of an interconnected array of microcontroller based subsystems. By having an power line data transceiver inside each subsystem, the shared power and data cabling can be reduced to a simple two line type, offering major installation cost reductions.



Power Line Data Transceiver Block Diagram



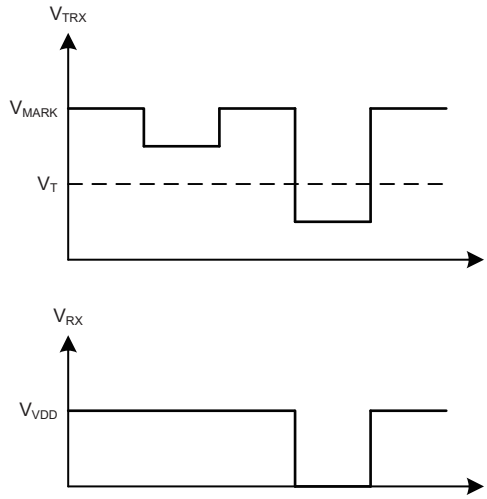
Power Line Data Transceiver System Block Diagram

Shared Power Line

All microcontroller based subsystems are connected together via the same two line power connection. The ground line is hardwired to each subsystem while the positive power line is connected to the VIN pin on the Power Line Data Transceiver. An internal Low Dropout Voltage Regulator within the Power Line Data Transceiver converts this input power supply voltage to a fixed voltage level which is supplied to the subsystem microcontroller and other circuit components. In this way when the power line voltage is changed due to the transmission or reception of data the subsystem circuits still continue to receive a regulated power supply.

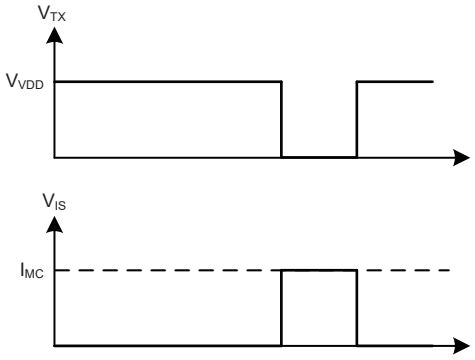
Data Transmission (From master controller to slave device)

Refer to the application circuit when reading the following description. The master controller transmits the data by modulate the positive power line (L+) voltage. Using this method should be pay attention to the noise tolerance of the device operating voltage and the TRX pin receiving data. As the Power Line Data Transceiver includes a voltage regulator which is used as the power supply to the subsystem units, then the subsystem power supply voltage will not be affected as long as the regulator minimum dropout voltage is maintained. Then a voltage modulation signal will be detected in the TRX pin to make the TRX pin voltage drop lower than the threshold voltage (V_T). However a reduction in the power supply will be detected by the CMP internal comparator.The output of this comparator is connected to RX line can be connected to a microcontroller input for use as a data signal.



Data Reception (From slave device to master controller)

Refer to the application circuit when reading the following description. The slave device can transmit data to the master controller by modulating the current on the power supply line. The slave device pulls the TX line voltage to a low level to enable the internal current modulator. The modulator will provide a constant current load by the transistor connected to the internal modulator OPA output NMOS terminal. The constant current load is supplied by the power line through the TRX pin, and can be adjusted by the R_S resistor connected on the IS pin. Therefore, the current modulation signals can be generated on the TRX pin by control the TX line voltage level. The current modulation signal can return to the master controller throuth the power supply line.



Current Modulator

The Power Line Data Transceiver device can modulate power line current by adding additional constant current source which is controlled by TX line. When the TX line is connected to low level, this current modulation function will be enabled. The modulation current can be calculated by the following formula:

$$I_{IS} = 1.5V / R_S$$

Application Considerations

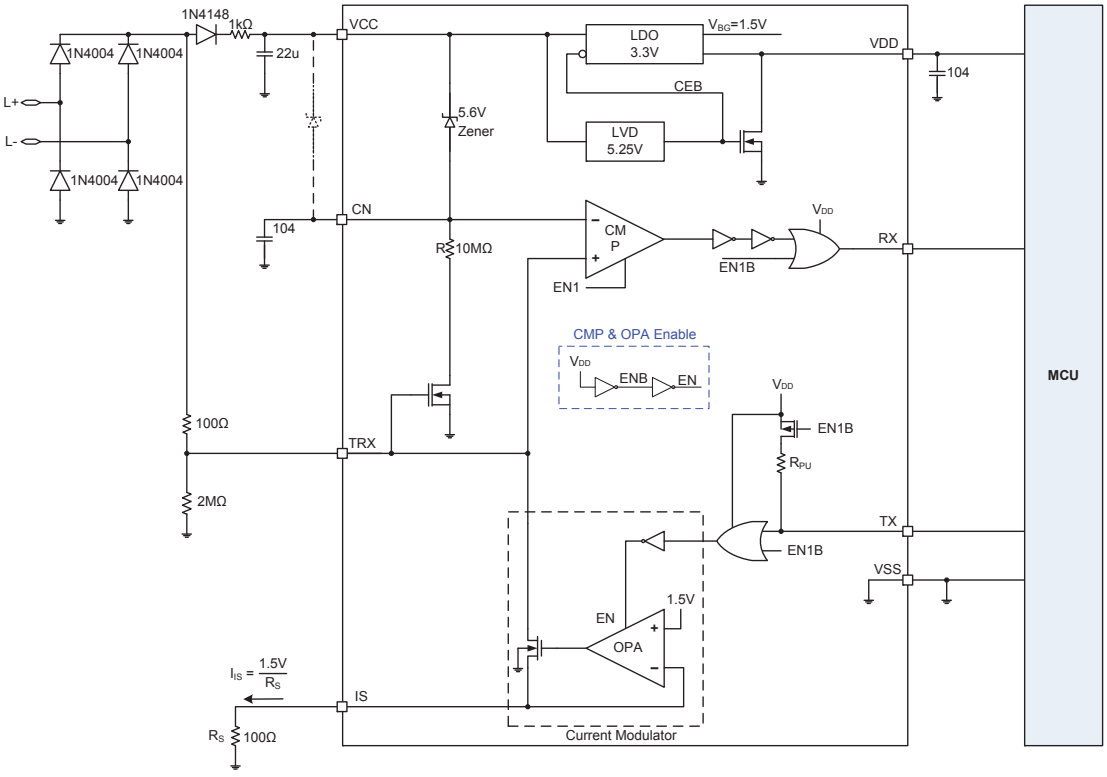
It is envisaged that the Power Line Data Transceiver will be used together with microcontroller based subsystems which will be required to provide two I/O pins for data transmission and reception. The MCU I/O line connected to the TX line must be setup as an output while the MCU I/O line connected to the RX line must be setup as an input.

Power impedance plays an important role in the power data transceiver applications, so it must be well defined to be used in reliable data transmit and receive operations.

The external components connected to the TRX pin must be carefully selected to ensure that an enough pulse duration time is occured on the RX line. Data transmission on the RX line can be detected using the MCU RXINT interrupt or by polling the PB6 line input status.

Common decoupling protection must be taken to ensure reliable operation.

Power Line Data Transceiver Application Circuits



Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains several external interrupt and internal interrupt functions. The external interrupt is generated by the action of the external INT pin, while the internal interrupts are generated by various internal functions such as the Power Line Data Transceiver, Timer Modules (TMs), Time Bases, Low Voltage Detector (LVD), EEPROM and the A/D Converter.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory. The registers fall into two categories. The first is the INTC0~INTC2 registers which setup the primary interrupts and the second is the INTEG register which setup the external interrupt trigger edge type and the RX data transmission detection interrupt trigger edge type.

Each register contains a number of enable bits to enable or disable individual registers as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an “E” for enable/disable bit or “F” for request flag.

Function	Enable Bit	Request Flag	Note
Global	EMI	—	—
INT Pin	INTE	INTF	—
RXINT	RXINTE	RXINTF	—
Time Base	TBnE	TBnF	n=0~1
LVD	LVE	LVF	—
A/D Converter	ADE	ADF	—
EEPROM	DEE	DEF	—
TM	STMnPE	STMnPF	n=0~1
	STMnAE	STMnAF	

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
INTC0	—	LVF	RXINTF	INTF	LVE	RXINTE	INTE	EMI
INTC1	STM0AF	STM0PF	DEF	ADF	STM0AE	STM0PE	DEE	ADE
INTC2	STM1AF	STM1PF	TB1F	TB0F	STM1AE	STM1PE	TB1E	TB0E

Interrupt Registers List

INTEG Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~2 **INT1S1~INT1S0**: Interrupt Edge Control for RXINT Line
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

Bit 1~0 **INT0S1~INT0S0**: Interrupt Edge Control for INT Pin
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

INTC0 Register

Bit	7	6	5	4	3	2	1	0
Name	—	LVF	RXINTF	INTF	LVE	RXINTE	INTE	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **LVF**: LVD Interrupt Request Flag
0: No request
1: Interrupt request

Bit 5 **RXINTF**: RXINT Interrupt Request Flag
0: No request
1: Interrupt request

Bit 4 **INTF**: External Interrupt Request Flag
0: No request
1: Interrupt request

Bit 3 **LVE**: LVD Interrupt Control
0: Disable
1: Enable

Bit 2 **RXINTE**: RXINT Interrupt Control
0: Disable
1: Enable

Bit 1 **INTE**: External Interrupt Control
0: Disable
1: Enable

Bit 0 **EMI**: Global Interrupt Control
0: Disable
1: Enable

INTC1 Register

Bit	7	6	5	4	3	2	1	0
Name	STM0AF	STM0PF	DEF	ADF	STM0AE	STM0PE	DEE	ADE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **STM0AF**: STM0 Comparator A Match Interrupt Request Flag
0: No request
1: Interrupt request

Bit 6 **STM0PF**: STM0 Comparator P Match Interrupt Request Flag
0: No request
1: Interrupt request

Bit 5 **DEF**: Data EEPROM Interrupt Request Flag
0: No request
1: Interrupt request

Bit 4 **ADF**: A/D Converter Interrupt Request Flag
0: No request
1: Interrupt request

Bit 3 **STM0AE**: STM0 Comparator A Match Interrupt Control
0: Disable
1: Enable

Bit 2 **STM0PE**: STM0 Comparator P Match Interrupt Control
0: Disable
1: Enable

Bit 1 **DEE**: Data EEPROM Interrupt Control
0: Disable
1: Enable

Bit 0 **ADE**: A/D Converter Interrupt Control
0: Disable
1: Enable

INTC2 Register

Bit	7	6	5	4	3	2	1	0
Name	STM1AF	STM1PF	TB1F	TB0F	STM1AE	STM1PE	TB1E	TB0E
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **STM1AF**: STM1 Comparator A Match Interrupt Request Flag
0: No request
1: Interrupt request

Bit 6 **STM1PF**: STM1 Comparator P Match Interrupt Request Flag
0: No request
1: Interrupt request

Bit 5 **TB1F**: Time Base 1 Interrupt Request Flag
0: No request
1: Interrupt request

Bit 4 **TB0F**: Time Base 0 Interrupt Request Flag
0: No request
1: Interrupt request

Bit 3 **STM1AE**: STM1 Comparator A Match Interrupt Control
0: Disable
1: Enable

Bit 2 **STM1PE**: STM1 Comparator P Match Interrupt Control
0: Disable
1: Enable

Bit 1 **TB1E**: Time Base 1 Interrupt Control
0: Disable
1: Enable

Bit 0 **TB0E**: Time Base 0 Interrupt Control
0: Disable
1: Enable

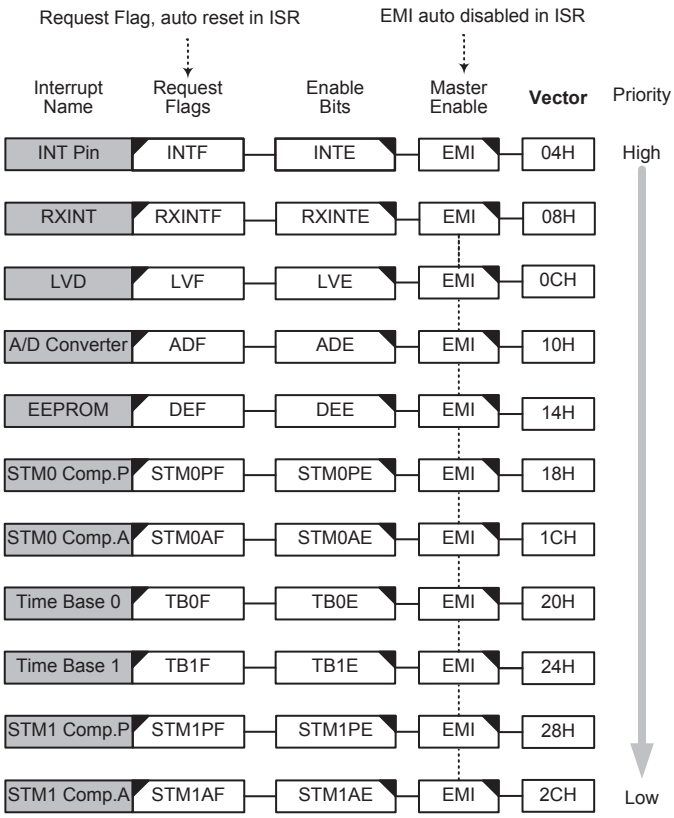
Interrupt Operation

When the conditions for an interrupt event occur, such as a TM Comparator P, Comparator A match or an EEPROM Write cycle ends etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector; if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a "JMP" which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with a "RETI", which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the accompanying diagrams with their order of priority. Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupt

The external interrupt is controlled by signal transitions on the pin INT. An external interrupt request will take place when the external interrupt request flag, INTF, is set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pins. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INTE, must first be set. Additionally the correct interrupt edge type must be selected using the INTEG register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their external interrupt enable bit in the corresponding interrupt register has been set and the external interrupt pin is selected by the corresponding pin-shared function selection bits. The pin must also be setup as an input by setting the corresponding bit in the port control register.

When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flag, INTF, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pins will remain valid even if the pin is used as an external interrupt input. The INTEG register can be used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

RX Data Transmission Detection Interrupt

The RX data transmission detection interrupt, abbreviated to the name RXINT interrupt, is controlled by signal transitions on the RX line. An RXINT Interrupt request will take place when the RXINT Interrupt request flag, RXINTF, is set, which occurs when the a data transmission is detected on the RX line of the Power line data transceiver. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and RXINT Interrupt enable bit, RXINTE, must first be set. When the interrupt is enabled, the stack is not full and a low voltage condition occurs, a subroutine call to the respective Interrupt vector, will take place. When the Interrupt is serviced, the RXINTF flag will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

The INTEG register can be used to select the type of active edge that will trigger the RXINT interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the RXINT interrupt function.

Timer Module Interrupts

The Standard type TMs each has two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. For all of the TM types there are two interrupt request flags and two enable control bits. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective TM Interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant Interrupt vector locations, will take place. When the TM interrupt is serviced, the TM interrupt request flags will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

LVD Interrupt

An LVD Interrupt request will take place when the LVD Interrupt request flag, LVF, is set, which occurs when the Low Voltage Detector function detects a low power supply voltage. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and Low Voltage Interrupt enable bit, LVE, must first be set. When the interrupt is enabled, the stack is not full and a low voltage condition occurs, a subroutine call to the respective Interrupt vector, will take place. When the Low Voltage Interrupt is serviced, the LVF flag will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

EEPROM Interrupt

An EEPROM Interrupt request will take place when the EEPROM Interrupt request flag, DEF, is set, which occurs when an EEPROM Write cycle ends. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and EEPROM Interrupt enable bit, DEE, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM Write cycle ends, a subroutine call to the respective EEPROM Interrupt vector will take place. When the EEPROM Interrupt is serviced, the DEF flag will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

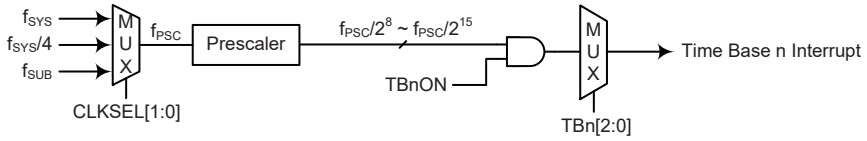
A/D Converter Interrupt

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and A/D Interrupt enable bit, ADE, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Converter Interrupt vector, will take place. When the interrupt is serviced, the A/D Converter Interrupt flag, ADF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

Time Base Interrupts

The function of the Time Base Interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happens their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI, and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically cleared, the EMI bit will also be automatically cleared to disable other interrupts.

The purpose of the Time Base Interrupt is to provide an interrupt signal at fixed time periods. Its clock source, f_{PSC}, originates from the internal clock source f_{SYS}, $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL1~CLKSEL0 bits in the PSCR register.



Time Base Interrupt (n=0~1)

PSCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source selection
00: f_{SYS}
01: $f_{SYS}/4$
1x: f_{SUB}

TB0C Register

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB0ON**: Time Base 0 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB02~TB00**: Select Time Base 0 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

TB1C Register

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB1ON**: Time Base 1 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB12~TB10**: Select Time Base 1 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though the device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pins or a low power supply voltage may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

It is recommended that programs do not use the “CALL” instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in SLEEP or IDLE Mode, the wake up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine. To return from an interrupt subroutine, either a RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Low Voltage Detector – LVD

The device has a Low Voltage Detector function, also known as LVD. This enabled the device to monitor the power supply voltage, V_{DD}, and provide a warning signal should it fall below a certain level. This function may be especially useful in battery applications where the supply voltage will gradually reduce as the battery ages, as it allows an early warning battery low signal to be generated. The Low Voltage Detector also has the capability of generating an interrupt signal.

LVD Register

The Low Voltage Detector function is controlled using a single register with the name LVDC. Three bits in this register, VLVD2~VLVD0, are used to select one of eight fixed voltages below which a low voltage condition will be determined. A low voltage condition is indicated when the LVDO bit is set. If the LVDO bit is low, this indicates that the V_{DD} voltage is above the preset low voltage value. The LVDEN bit is used to control the overall on/off function of the low voltage detector. Setting the bit high will enable the low voltage detector. Clearing the bit to zero will switch off the internal low voltage detector circuits. As the low voltage detector will consume a certain amount of power, it may be desirable to switch off the circuit when not in use, an important consideration in power sensitive battery powered applications.

LVDC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	LVDO	LVDEN	VBGEN	VLVD2	VLVD1	VLVD0
R/W	—	—	R	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **LVDO**: LVD Output Flag
0: No Low Voltage Detect
1: Low Voltage Detect

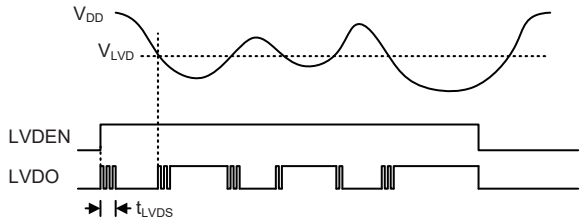
Bit 4 **LVDEN**: Low Voltage Detector Control
0: Disable
1: Enable

Bit 3 **VBGEN**: Bandgap Buffer Control
0: Disable
1: Enable
Note that the Bandgap circuit is enabled when the LVD or the LVR function is enabled or when the VBGEN bit is set high.

Bit 2~0 **VLVD2~VLVD0**: Select LVD Voltage
000: 2.0V
001: 2.2V
010: 2.4V
011: 2.7V
100: 3.0V
101: 3.3V
110: 3.6V
111: 4.0V

LVD Operation

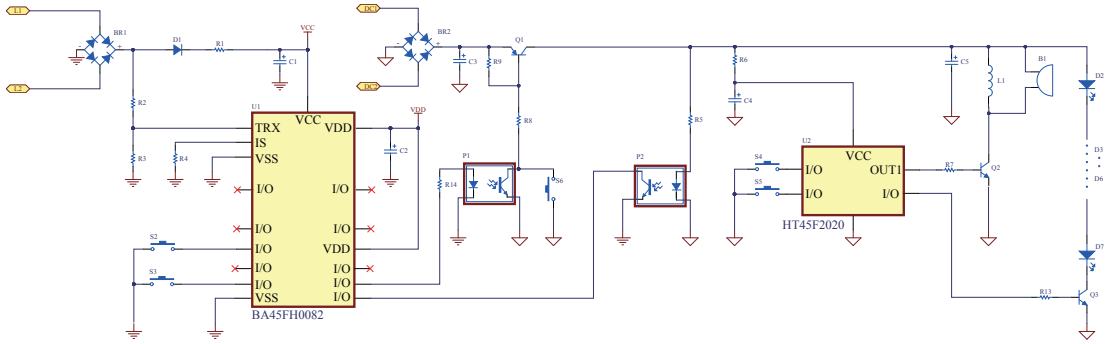
The Low Voltage Detector function operates by comparing the power supply voltage, V_{DD}, with a pre-specified voltage level stored in the LVDC register. This has a range of between 2.0V and 4.0V. When the power supply voltage, V_{DD}, falls below this pre-determined value, the LVDO bit will be set high indicating a low power supply voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. After enabling the Low Voltage Detector, a time delay t_{LVDS} should be allowed for the circuitry to stabilise before reading the LVDO bit. Note also that as the V_{DD} voltage may rise and fall rather slowly, at the voltage nears that of V_{LVD}, there may be multiple bit LVDO transitions.



LVD Operation

The Low Voltage Detector also has its own interrupt, providing an alternative means of low voltage detection, in addition to polling the LVDO bit. The interrupt will only be generated after a delay of t_{LVD} after the LVDO bit has been set high by a low voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. In this case, the LVF interrupt request flag will be set, causing an interrupt to be generated if V_{DD} falls below the preset LVD voltage. This will cause the device to wake-up from the IDLE Mode, however if the Low Voltage Detector wake up function is not required then the LVF flag should be first set high before the device enters the IDLE Mode.

Application Circuits



Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 4MHz system oscillator, most instructions would be implemented within 1μs and branch or call instructions would be implemented within 1μs. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be "CLR PCL" or "MOV PCL, A". For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of three kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction "RET" in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be set as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the "HALT" instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The following table depicts a summary of the instruction set categorised according to function and can be consulted as a basic instruction reference using the following listed conventions.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV
ADDM A,[m]	Add ACC to Data Memory	1Note	Z, C, AC, OV
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV
ADCM A,[m]	Add ACC to Data memory with Carry	1Note	Z, C, AC, OV
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1Note	Z, C, AC, OV
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1Note	Z, C, AC, OV
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1Note	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1Note	Z
ORM A,[m]	Logical OR ACC to Data Memory	1Note	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1Note	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1Note	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1Note	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1Note	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1Note	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1Note	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1Note	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1Note	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1Note	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1Note	None
SET [m].i	Set bit of Data Memory	1Note	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1Note	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1Note	None
SZ [m].i	Skip if bit i of Data Memory is zero	1Note	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1Note	None
SIZ [m]	Skip if increment Data Memory is zero	1Note	None
SDZ [m]	Skip if decrement Data Memory is zero	1Note	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1Note	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1Note	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page) to TBLH and Data Memory	2Note	None
TABRDC [m]	Read table (current page) to TBLH and Data Memory	2Note	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2Note	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1Note	None
SET [m]	Set Data Memory	1Note	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
CLR WDT1	Pre-clear Watchdog Timer	1	TO, PDF
CLR WDT2	Pre-clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1Note	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.
2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.
3. For the "CLR WDT1" and "CLR WDT2" instructions the TO and PDF flags may be affected by the execution status. The TO and PDF flags are cleared after both "CLR WDT1" and "CLR WDT2" instructions are consecutively executed. Otherwise the TO and PDF flags remain unchanged.

Instruction Definition

ADC A,[m] Add Data Memory to ACC with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C

ADCM A,[m] Add ACC to Data Memory with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C

ADD A,[m] Add Data Memory to ACC

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m]

Affected flag(s) OV, Z, AC, C

ADD A,x Add immediate data to ACC

Description The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.

Operation ACC ← ACC + x

Affected flag(s) OV, Z, AC, C

ADDM A,[m] Add ACC to Data Memory

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m]

Affected flag(s) OV, Z, AC, C

AND A,[m] Logical AND Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" [m]

Affected flag(s) Z

AND A,x Logical AND immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" x

Affected flag(s) Z

ANDM A,[m] Logical AND ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation [m] ← ACC "AND" [m]

Affected flag(s) Z

CALL addr Subroutine call

Description: Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.

Operation: Stack ← Program Counter + 1
Program Counter ← addr

Affected flag(s): None

CLR [m] Clear Data Memory

Description: Each bit of the specified Data Memory is cleared to 0.

Operation: [m] ← 00H

Affected flag(s): None

CLR [m].i Clear bit of Data Memory

Description: Bit i of the specified Data Memory is cleared to 0.

Operation: [m].i ← 0

Affected flag(s): None

CLR WDT Clear Watchdog Timer

Description: The TO, PDF flags and the WDT are all cleared.

Operation: WDT cleared
TO ← 0
PDF ← 0

Affected flag(s): TO, PDF

CLR WDT1 Pre-clear Watchdog Timer

Description: The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunction with CLR WDT2 and must be executed alternately with CLR WDT2 to have effect. Repetitively executing this instruction without alternately executing CLR WDT2 will have no effect.

Operation: WDT cleared
TO ← 0
PDF ← 0

Affected flag(s): TO, PDF

CLR WDT2 Pre-clear Watchdog Timer

Description: The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunction with CLR WDT1 and must be executed alternately with CLR WDT1 to have effect. Repetitively executing this instruction without alternately executing CLR WDT1 will have no effect.

Operation: WDT cleared
TO ← 0
PDF ← 0

Affected flag(s): TO, PDF

CPL [m] Complement Data Memory

Description: Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.

Operation: $[m] \leftarrow \overline{[m]}$

Affected flag(s): Z

CPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow \overline{[m]}$

Affected flag(s) Z

DAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.

Operation [m] ← ACC + 00H or
[m] ← ACC + 06H or
[m] ← ACC + 60H or
[m] ← ACC + 66H

Affected flag(s) C

DEC [m] Decrement Data Memory

Description Data in the specified Data Memory is decremented by 1.

Operation [m] ← [m] − 1

Affected flag(s) Z

DECA [m] Decrement Data Memory with result in ACC

Description Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] − 1

Affected flag(s) Z

HALT Enter power down mode

Description This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.

Operation TO ← 0
PDF ← 1

Affected flag(s) TO, PDF

INC [m] Increment Data Memory

Description Data in the specified Data Memory is incremented by 1.

Operation [m] ← [m] + 1

Affected flag(s) Z

INCA [m] Increment Data Memory with result in ACC

Description Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] + 1

Affected flag(s) Z

JMP addr Jump unconditionally

Description The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.

Operation Program Counter ← addr

Affected flag(s) None

MOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

Operation ACC ← [m]

Affected flag(s) None

MOV A,x Move immediate data to ACC

Description The immediate data specified is loaded into the Accumulator.

Operation ACC ← x

Affected flag(s) None

MOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

Operation [m] ← ACC

Affected flag(s) None

NOP No operation

Description No operation is performed. Execution continues with the next instruction.

Operation No operation

Affected flag(s) None

OR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ [m]

Affected flag(s) Z

OR A,x Logical OR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ x

Affected flag(s) Z

ORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″OR″ [m]

Affected flag(s) Z

RET Return from subroutine

Description The Program Counter is restored from the stack. Program execution continues at the restored address.

Operation Program Counter ← Stack

Affected flag(s) None

RET A,x Return from subroutine and load immediate data to ACC

Description The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.

Operation Program Counter ← Stack
ACC ← x

Affected flag(s) None

RETI Return from interrupt

Description The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.

Operation Program Counter ← Stack
EMI ← 1

Affected flag(s) None

RL [m] Rotate Data Memory left

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← [m].7

Affected flag(s) None

RLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s) None

RLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s) C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s) C

RR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s) None

RRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s) None

RRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s) C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s) C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m] − C

Affected flag(s) OV, Z, AC, C

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m] − C

Affected flag(s) OV, Z, AC, C

SDZ [m] Skip if decrement Data Memory is 0

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] − 1
Skip if [m]=0

Affected flag(s) None

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation ACC ← [m] − 1
Skip if ACC=0

Affected flag(s) None

SET [m] Set Data Memory

Description Each bit of the specified Data Memory is set to 1.

Operation [m] ← FFH

Affected flag(s) None

SET [m].i Set bit of Data Memory

Description Bit i of the specified Data Memory is set to 1.

Operation [m].i ← 1

Affected flag(s) None

SIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] + 1
Skip if [m]=0

Affected flag(s) None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m] + 1
Skip if ACC=0

Affected flag(s) None

SNZ [m].i Skip if bit i of Data Memory is not 0

Description If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i ≠ 0

Affected flag(s) None

SUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUB A,x Subtract immediate data from ACC

Description The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − x

Affected flag(s) OV, Z, AC, C

SWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s) None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s) None

SZ [m] Skip if Data Memory is 0

Description If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation Skip if [m]=0

Affected flag(s) None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m]
Skip if [m]=0

Affected flag(s) None

SZ [m].i Skip if bit i of Data Memory is 0

Description If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i=0

Affected flag(s) None

TABRD [m] Read table (specific page) to TBLH and Data Memory

Description The low byte of the program code (specific page) addressed by the table pointer pair (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

TABRDC [m] Read table (current page) to TBLH and Data Memory

Description The low byte of the program code (current page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

XOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ [m]

Affected flag(s) Z

XORM A,[m] Logical XOR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″XOR″ [m]

Affected flag(s) Z

XOR A,x Logical XOR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ x

Affected flag(s) Z

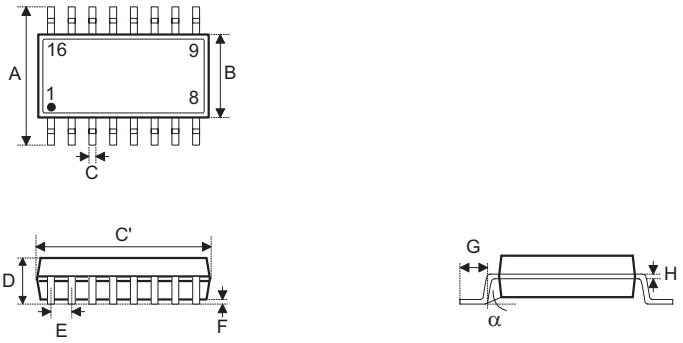
Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website for the latest version of the Package/Carton Information.

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

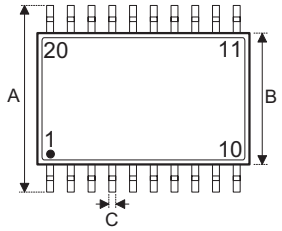
16-pin NSOP (150mil) Outline Dimensions

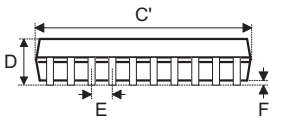


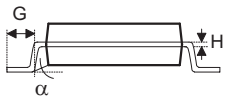
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.020
C’	—	0.390 BSC	—
D	—	—	0.069
E	—	0.050 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.31	—	0.51
C’	—	9.90 BSC	—
D	—	—	1.75
E	—	1.27 BSC	—
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

20-pin SSOP (150mil) Outline Dimensions







Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.008	—	0.012
C’	—	0.341 BSC	—
D	—	—	0.069
E	—	0.025 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.20	—	0.30
C’	—	8.66 BSC	—
D	—	—	1.75
E	—	0.635 BSC	—
F	0.10	—	0.25
G	0.41	—	1.27
H	0.10	—	0.25
α	0°	—	8°